

144WHz TRANSCEIVER

INSTRUCTIONS MANUAL



STANDARD COMMUNICATIONS CORP.

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We are confident that you will be entirely satisfied with your 144 MHz Transceiver Model C8800. Our very strict quality control and inspection ensure that each transceiver unit left the factory in perfect condition. If the unit is damaged or fails to operate properly, immediately contact your dealer.

To obtain the best performance and longest use from your transceiver, study these instructions carefully.

ACCESSORIES

Hand microp		II HITH		
control MP				
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* Stand			and the second second	
* Mobile brack			17 P. S.	
* Nine-pin plus				13.11
* Bracket mou	nting screw			
* Operation ha	ndbock			
* Schematic di	agram , ,			

INSTRUCTION MANUAL SECTION

1. PRECAUTIONS

INSTALLATION PRECAUTIONS

- Install your transceiver in a dry, dust-free and wellventilated place. The unit should not be subjected to extremely high temperatures or humidity. It must not, under any circumstances, be exposed to direct sunlight.
- Provide adequate space behind and under the unit for free circulation of air.
- In a mobile installation, exercise special care to allow enough space behind the unit for adequate heat-dissipation from the heat sink. Take measures to ensure that the unit is not subjected to excessive vibration or shock during operation.

POWER SUPPLY

 The C8800 is designed to operate on 13.8 volt DC or commercial AC power. Do not connect this unit to a 24 volt DC power supply {E.g., batteries used in large vehicles}.

The transceiver is equipped with an internal memory back-up system. For further details of the system, read paragraph 4.2.4.

When you wish to power your transceiver from a commercial AC outlet, use the operationally available power Supply Attachment.

ANTENNA

To obtain the best results from the C8800 Transceiver, use an antenna which has a proven performance. The SWR of your antenna should be adjusted to 1.5 or below. If SWR adjustment is inadequate, the transmission power may fail to reach the specified value.

If the antenna SWR is increased to more than 4 or 5, an internal protection circuit automatically operates to reduce transmission power and protect final transistors.

2. FEATURES

The C8800 Mobile Transceiver features innovative microcomputer-sided operations. The C8800's built-in microcomputer memorizes, thinks, and makes decisions for quick and correct channel control.

The microcomputer offers the following functions:

- Capable of memorizing, or programming any five (5) frequencies (max.).
- Scans up and down the five stored channel frequencies.
- Scans up and down the five stored channels plus two call channels.
- Scans up and down frequencies from 144.00 MHz through 145.995 MHz at a 5 kHz or 25 kHz interval.
- 5. Automatically searches for busy channels.
- 6. Automatically searches for vacant channels.
- Two switchable scanning speeds are provided.
- Two frequency-scanning intervals of 5 kHz and 25 kHz are provided.
- A higher priority is given to the two call channels (145.50 MHz and 145.55 MHz).

•

SUPERIOR OPERABILITY AND MANY OTHER FEATURES

Memory back-up feature:

With this feature, pre-programmed channel frequencies are maintained in the memory even when the main power to the unit is switched OFF. If the supply voltage is abnormally low, an internal DC-to-DC converter initiates operation to maintain the back-up voltage at a constant level, to keep the stored frequency data intact.

* 400 channels selectable:

Up to 400 channels can be selected using the noncontact channel selector which has 24 steps per rotation (80 channels at 25 kHz interval, and 400 channels at 5 kHz interval).

* Microphone with a frequency up-down control:

The attached hand microphone was a built-in frequency up-down control for easy and continuous channel selection.

* Easy-to-operate, sloping control panel:

The C8800 is designed ergonomically and features a sloping control panel for ease of operating controls and a carefully thought out panel layout.

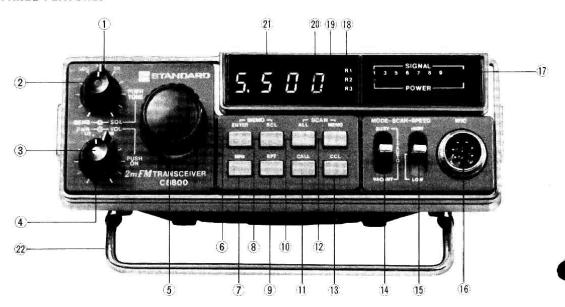
OTHER FEATURES

- A built-in receiver booster with three-stepped reception sensitivity control for DX operation.
- Built-in general call frequency of 145.50 MHz and mobile call frequency of 145.55 MHz available.
- * A unique signal & power meter comprised of 9 LEDs.
- Easy-on-the-eyes, 4 digit green LED frequency readout.
- Superior intermodulation characteristic achieved with the introduction of the herical cavity.
- * Large 8 cmφ built-in loudspeaker.
- A line-noise filter shuts out any noise on the AC power line.
- A single VCO serving for both reception and transmission.
- Transmission power switchable between 1 watt and 10 watts.
- The "direct" VCO circuit reduces generation of spurious noise.
- The APC (Auto Power Control) circuit protects final transistors from variations of antenna SWR or supply voltage.

- The mic-amplifier uses the VOGAD IC, which permits modulation of a high mean-modulation degree and low distortion.
- A piezo-electric buzzer for audible checking incorporated on keyboard and UP/DWN control operations.
- * Built-in tone burst generator for repeater driving.
- Built-in frequency-shift circuit, for repeater.

3. PANEL FEATURES

FRONT PANEL FEATURES



SENS (Sensitivity) SELECTOR

The SENS selector is used for reception sensitivity selection (DX, NOR, and LOC positions). The DX position is for long-distance communication, the NOR position for middle-distance communication, and the LOC position for local communication.

2 PUSH TONE/SQL (Squelch) CONTROL

This knob serves a dual purpose: squelch control and tone-burst switch. While this knob is depressed, the transmitter transmits a tone-burst signal for repeater driving (Tone frequency: 1750 Hz). The squelch control is used to eliminate white noise heard on FM reception channels when no signals is present. Normally, this control should be turned gradually clockwise until the white noise disappears.

PUSH ON/VOL CONTROL

This knob also serves a dual purpose: power switch and volume control. A first depression of this knob turns the power to the unit ON, and the second depression turns it OFF. Clockwise rotation of this control increases output volume level.

PWR SELECTOR

The PWR selector selects transmission power between 1 watt and 10 watts. The 1 W position of this switch will be found to be best for local communication.

6 CHANNEL SELECTOR

Clockwise rotation of this selector increases channel frequency at either a 5 kHz or 25 kHz interval.

6 MEMO ENTER BUTTON

Pressing this button stores the desired frequency data in the internal memory. The memory has a capacity for storing up to 5 frequencies.

Use the CHANNEL selector or the UP/DWN control on the microphone to preset the desired frequency before pressing this MEMO ENTER button.

MHz BUTTON

A simple depression of this button switches the frequency band from 144 MHz to 145 MHz and vice versa.

MEMO RCL BUTTON

Pressing this button recalls stored frequency data. Each depression of this button recalls stored frequencies sequentially from M1 through M5.

RPT (Repeater) BUTTON

This key is used to select Simplex, Repeater-1, Repeater-2, or Repeater-3.

(II) SCAN ALL BUTTON

While this button is depressed, the entire 144 MHz or 145 MHz frequency band is scanned at a 5 kHz or 25 kHz interval.

(II) CALL BUTTON

The CALL button gives priority in frequency selection to call frequencies 145.50 MHz and 145.55 MHz. The first depression of this button selects 145.50 MHz, and the second depression selects 145.55 MHz.

P SCAN MEMO BUTTON

Pressing this button initiates scanning stored frequencies sequentially from M1 through M5. If the CALL key is depressed before this SCAN MEMO button is depressed, the CALL channel frequencies C1 and C2 (145.50 MHz and 145.50 MHz, respectively) can be added to the scanning sequence, thus establishing a new sequence C1 - C2 - M1 - M2 - M3 - M4 - M5.

(B) CCL BUTTON

Pressing the CCL button resets operation mode to the initial state.

SCAN MODE SWITCH

This switch is used to search for busy or vacant channels during frequency scanning. The BUSY position of this switch initiates a search for busy channels, and the VACANT position a search for vacant channels.

SCAN SPEED SWITCH

This switch is used to select frequency scanning speeds:
HI position: 0.25 second per step
LOW position: 2.0 second per step

MIC JACK

The MIC jack accepts the attached hand microphone.

TSIGNAL & POWER METER

This unique 9-LED meter indicates signal strength in the reception mode, and transmission power in the transmission mode.

1 R1 (Repeater-1) INDICATOR

When this R1 indicator is lit, the transmission frequency is reduced by 600 kHz with respect to the reception frequency. If transmission is tried at a frequency below 144.600 MHz, the transmitter output is shut down and the frequency readout displays "OFF".

R2 (Repeater-2) INDICATOR

When this R2 indicator is lit, the transmission frequency is increased by 600 kHz with respect to the reception frequency. If transmission is tried at a frequency above 145.400 MHz, the transmitter output is shut down and the frequency readout displays "OFF".

(Repeater-3)

- * By providing an optional quartz crystal in the C8800's PLL circuit, transmission frequency can be shifted arbitrarily with reference to the readout frequency (received frequency). The shifted transmission frequency is, however, not displayed.
- * When no crystal is provided in the circuit, the transmitter section remains inoperative while the receiver section operates at the readout frequency.
- For details of the required quartz crystal specifications, see paragraph "X'tal for Repeater-3".

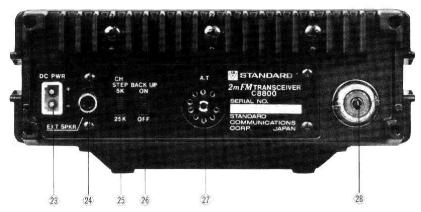
TREQUENCY READOUT

When a signal of, say, 145.50 MHz is received, this frequency readout displays the last four digits as "5.500". If the CALL button is depressed, the least significant digit of the readout is replaced with "C" to indicate that the CALL function is activated.

2 STAND

The unit can be placed on the stand when it is operated as a fixed station.

REAR PANEL FEATURES



(A) DC 13.8 V

This receptacle accepts a DC 13.8 V power supply. Connect the supplied connection cord with care to ensure the correct polarity.

EXT SPKR JACK

This jack accepts an external speaker with an impedance of $4\sim8$ ohms.

CH STEP SWITCH

.ne CH STEP switch is used to select a single frequency step interval of either 5 kHz or 25 kHz.

BACK-UP SWITCH

Activating this switch provides the internal memory with a back-up power supply to maintain stored frequency

ANT CONNECTOR

A.T. (Accessory Terminal)

to the paragraph "Accessory Terminal".

The ANT connector accepts an antenna with an impedance of 50 ohms.

data even when the main power to the unit is switched

OFF. If the transceiver unit is left unused for a long

period of time, be sure to set this switch at the OFF posi-

For details of the pin configuration of this terminal, refer

■ HAND MICROPHONE

PREQ. UP-DOWN CONTROL

This control initiates continuous up and down scanning of channel frequencies.

1 PTT BUTTON

Pressing this PTT (Press-To-Talk) button puts the transceiver in the transmission mode.



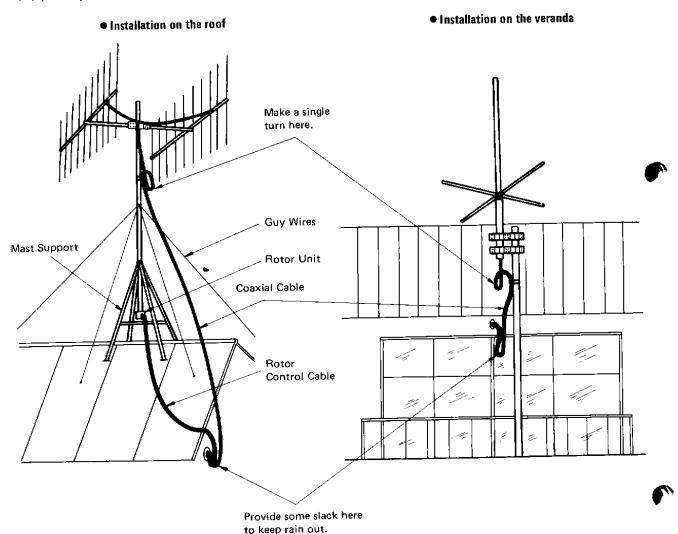
4. INSTALLATION

4.1 FIXED STATION

4.1.1 INSTALLING THE ANTENNA

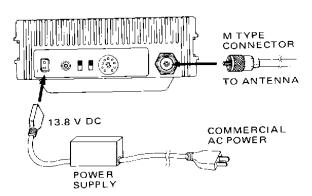
The type and method of installation of the outdoor antenna you use will greatly affect transmission and reception performances of your transceiver. Carefully select an antenna which will provide the best performance, and adjust carefully after installation.

To prevent lead-in signal loss, use as short an antenna lead-in cable as possible. Recommended cable type is the 5D-2V for up to 10 meters, and the 8D-2V or 10D-2V for up to 30 meters.



4.1.2 POWER SUPPLY

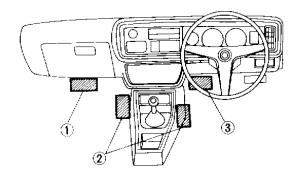
When supplying power from the wall outlet, use the power supply unit (optional accessory).



4.2 MOBIL TRANSCEIVER

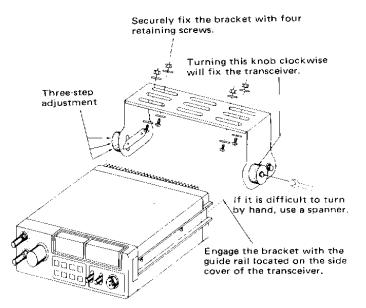
4.2.1 INSTALLING THE TRANSCEIVER

- Installation position
 - Below glove box
 - Beside center console box
 - Below the dashboard



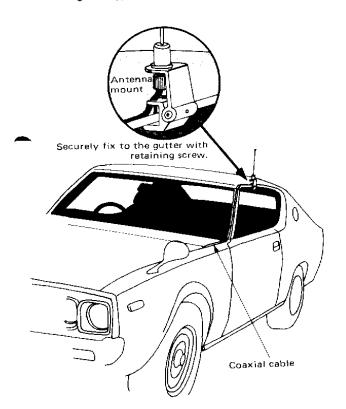
■ Installing with bracket (provided)

With the bracket, the reveiver can be positioned freely and the angle of the transceiver can be changed in three steps.

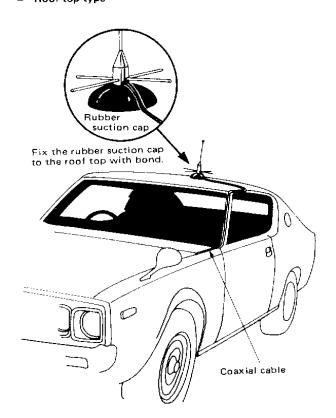


4.2.2 INSTALLING ANTENNA

■ Roof gutter type

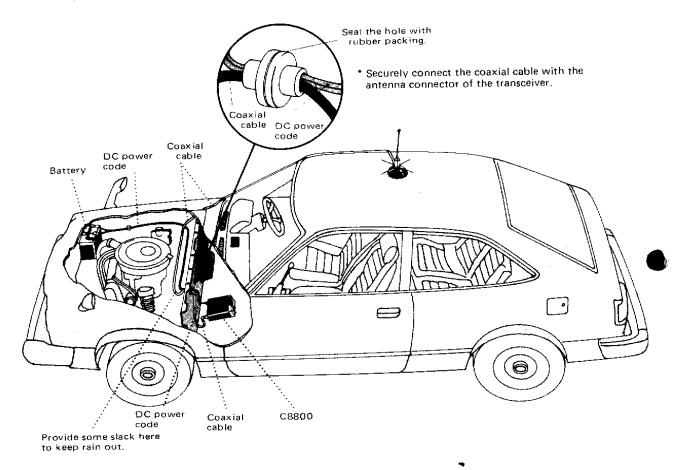


■ Roof top type



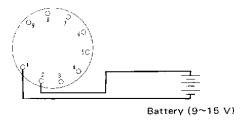
4,2,3 CONNECTING THE COAXIAL CABLE

Routing through the bonnet



4.2.4 CONNECTING THE POWER CODE

Connect the power code to the battery. If the BACK UP switch on the rear plate is turned ON, the memory is not erased when the C8800 is turned OFF. If the power cord is connected to a wire which is coupled to the engine key, the BACK UP switch does not function. When a battery (9 \sim 15 V) is connected between the 1P (Gnd) and 2P(+) of the ACC terminal, turning ON the BACK UP switch will retain the memory.



NOTE:

Fix the coaxial cable with tape so that the cable does not come in contact with the hot engine.

Some lines do not supply power when the starter is rotated. After checking with a multimeter, connect to a line which supplies power when the starter is rotated.

5. MICROCOMPUTER-AIDED OPERATION

The following section of the manual gives you a description of the microcomputer-aided operation of your transceiver unit in some detail.

5.1 PRECAUTIONS

The C8800 VHF Transceiver is capable of transmitting varied types radio waves. Use utmost care to avoid any trouble in comfort to your local regulations.

SSB

SSB

2m Band Plan (L.A.R.U. Region 1) CW MHz Allocation 144.000-144.010 E-M-E 144.050 CW calling 144.100 CW random ms 144,150 Upper limit CW exclusive 144.200 SSB random ms 144.300 SSB calling 144.500 SSTV calling 144.600 RTTY calling 144.700 FAX calling 144.900 Regional beacons centre 145.000-145.225 Repeater input - R0 to R9 RTTY (local) 145,300 145,500 Mobile calling 145.500 (S20), 145.525 (S21) FM simplex

Table 1. VHF Band Plans

145.550 (S22),

145.575 (S23)

145.600-145.825

5.2 MICROCOMPUTER OPERATION

(1) SELECTING SCANNING INTERVALS

The desired frequency scanning of either 5 kHz/step or 25 kHz/step is selected with the STEP switch on the rear of the unit.

FM simplex

Repeater output

or Output

(2) PWR AND BACK-UP SWITCHES

- When the power to the unit is turned ON, the internal microcomputer program first selects a channel frequency of 145.00 MHz.
- b. When the unit is powered directly from your car battery, turning OFF the power to the unit with the BACK UP switch set to ON will cause the microcomputer to store the state immediately before the power is turned OFF, and when the power to the unit is again turned ON, the unit restores the state immediately before the power was turned OFF (the scanning condition is, however, not memorized).

(ex.) 1. When channel frequency is set to 145.525 MHz:



→ Power **OFF** →

Power **ON** →



2. When channel frequency is set to 5.50c:



→ Power OFF →

Power ON →



NOTES:

ALL MODES

 Established simplex frequencies on repeater output channels may be retained.

MODES

REPEATER INPUT 45.845

SPACE

- 2. The segment 145.250-145.500 MHz may be allocated, if desired, to FM channels.
- 3. No regional planning for beacons of erp less than 50 W.
- 4. Regional planning fg beacons of erp more than 50 W.
- CW permitted over v-hole band, CW exclusive 144.0-144.150 MHz.
- Channelized nets should not operate in this portion at any time.
- Local traffic should operate above 145 MHz during contents and band openings.

(3) FREQUENCY SELECTION

Channel frequencies can be selected with the CHANNEL selector on the front panel of the unit or with the UP-DOWN control on the Hand Microphone.

- * Channel selection using the UP-DOWN control on the mic:
 - a. The Hand Microphone (MP-716) supplied with the C8800 Transceiver is equipped with a channel frequency UP-DOWN control. Pressing and holding the control switch in the UP or DOWN position scans the channels.
 - When the UP-DOWN switch is released, the channel scan stops at the frequency currently being received.
 - Holding the UP-DOWN control switch for less than 0.5 second shifts channel scan to the next channel where it stops.
 - d. While the UP-DOWN control switch is activated, all other key operations are desabled, except for the Press-To-Talk (PTT) button on the microphone which stops channel scanning.
 - e. When the ALL, MEMO, or CALL button is depressed, the UP-DOWN control switch is ineffective. While the transceiver is operating in the transmission mode, the UP-DOWN control switch is also ineffective.

(4) HOW TO PROGRAM CHANNEL FREQUENCIES

A. Initial frequency programming

The C8800 incorporates five memory units M1, M2, M3, M4, and M5 each capable of storing up to one frequencies i.e. five frequencies in all. To store the desired frequency in each memory unit, follow the procedure given below:

Storing frequency data in memory M1

 a. Press key RCL to recall the content of memory M1. (Before the key is pressed, the frequency readout will read "145.000 MHz".)

When memory is vacant:



Blink

(The dot at bottom left of LSD will blink to indicate that memory M1 is vacant).

b. Tune to the desired frequency by moving the CHAN-NEL selector on the front panel of the unit or the UP-DOWN control on the Hand Microphone. (E.g. 145.025 MHz)

The display will read:



Blinks

 Pressing the ENTER, key stores the frequency data in memory M1.



Lights up

 d. Press the RCL key again to check the frequency data stored in memory M1.



Storing frequency data in memory M2

 a. Pressing the RCL key again will display the content of memory M2.

When memory M2 is vacant:



Blinks

b. Tune to the frequency to be stored in M2 with the CHANNEL selector or UP-DOWN control. (E.g. 145.050 MHz).



Blinks

 Press the ENTER button to store the frequency data in memory M2.



Lights up

d. Press the RCL key to check the frequency data stored in memory M1.



 e. Press the RCL key again to check the frequency data stored in memory M2.



Storing frequency data in memory M3

a. Press the RCL button to display the content of memory M3 to the frequency readout.
 When memory M3 is vacant:



Blinks

 Tune to the frequency to be stored in M3 with the CHANNEL selector or UP-DOWN control. (E.g. 145.075 MHz).



Blinks

 Press the ENTER button to store the frequency data in memory M3.



Lights up

d. Press the RCL button to check the frequency data stored in memory M1.



 e. Press the RCL button again to check the frequency data stored in memory M2.



 Press the RCL button a third time to check the content of memory M3.



Storing frequency data in memory M4

a. Press the RCL button to display the content of memory M4.



Blinks

 Tune to the desired frequency to be stored in M4 by controlling the CHANNEL selector or UP-DOWN control. (E.g. 145.100 MHz)



Blinks

c. Press the ENTER button to store the frequency data in memory M4.



Lights up

d. Press the RCL button to check the content of M1.



 e. Press the RCL button again to check the content of memory M2.



f. Press the RCL button once again to check the content of M3.



g. And finally press the RCL button a fourth time to check the content of M4.



Storing frequency data in memory M5

a. Press the RCL button to display the content of memory M5.



Blink

 Tune to the frequency to be stored in M5 with the CHANNEL selector or UP-DOWN control. (E.g. 145.125 MHz)



Blinks

 Press the ENTER button to store the frequency data in memory M5.



Lights up

d. Press the RCL button to check the content of memory M1.



 e. Press the RCL button again to check the content of memory M2.



 Press the RCL button once again to check the content of memory M3.



Press the RCL button once again to check the content of memory M4.



 And finally press the RCL button a fifth time to check the content of memory M5.



(5) STORING REPEATER FUNCTIONS R1, R2, AND R3 TOGETHER WITH FREQUENCY DATA

Storing procedure is much the same as that for frequencies.

- a. Press the RCL button to recall the content of M1. (This will display the M1 content with the dot blinking.)
- Tune to the desired frequency (the frequency will be displayed with the dot blinking).
- c. Press the RPT button to select R1, R2, or R3 (the memory content will be displayed with the dot blinking).
- d. Press the ENTER button. This will store the selected repeater function in memory M1 together with the preset frequency (the memory content will be displayed with dot lit up).
- e. Press the RCL button to check the repeater function and frequency data stored in memory M1 (the memory content will be displayed with the dot lit up).

Other repeater functions can be stored in memories M2 through M5 in the same way as described above.

(6) HOW TO CHANGE STORED FREQUENCIES

Frequencies stored in the memory can be easily replaced with other frequencies as described in the following example:

E.g. Changing the frequency stored in M2:

(This example shows a case where frequency data of 145.050 MHz stored in **M2** is replaced with 145.150 MHz.)

 a. Press the RCL button twice to recall the content of memory M2 on the display.

(When 145.050 MHz is stored:)



Lit up

 b. Tune to the desired replacement frequency with the CHANNEL selector or UP-DOWN control. (E.g. 145.150 MHz)

Blinks

Press the ENTER button. This will replace the old frequency data in M2 with the new data of 145.150 MHz.



Lights up

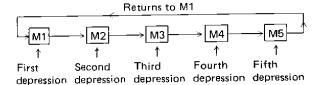
d. Press the RCL button twice to check that the new data is actually stored in memory M2.



Lit up

(7) HOW TO RECALL STORED FREQUENCIES

a. Pressing the RCL button once to recall the content of memory M1 on the readout. The number of times the RCL button is pressed corresponds to the number of the memory you wish to recall.



The sixth depression of the $\boxed{\textbf{RCL}}$ button returns the recall sequence to M1.

The recall operation takes higher priority over **CHANNEL** selector and scanning operation.

b. However, when the CALL key is depressed and 145.50c or 145.55c is displayed, the RCL function is ineffective. Press the CCL button to clear the CALL state and restore the RCL function.

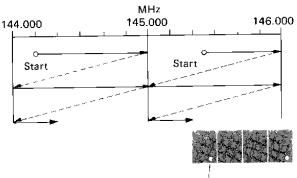
c. When memory content is recalled on the display by RCL operation, press the CCL button to clear the RCL function and bring back the data displayed before the RCL button was depressed.

(8) FREQUENCY SCANNING

A. How to scan the entire frequency band:

The channel frequency scanning modes include entire frequency band scanning and memory frequency scanning. There are three scan stop modes.

a. Scanning the entire 144 MHz or 145 MHz band: Pressing the ALL button starts entire frequency band scanning. The frequency is scanned upward from an arbitrary starting frequency as illustrated below.



During scanning, this dot blinks at an interval of approx. 1 sec.

Scanning period

Channel Switch position	25 kHz step (1 MHz) 40 channel	5 kHz step (1 MHz) 200 channel
Fast Scan	Approx. 10 sec.	Approx. 50 sec.
Slow Scan	Approx, 1 min. 20 sec.	Approx. 6 min. 40 sec.

- b. To search for busy channels:
 - * Set the MODE switch on the front panel of the unit to the BUSY position.
 - * Adjust the SQUELCH control to eliminate FM noise.
 - * Scanning is stopped at the frequency at which a signal is present.



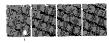
 Scanning is automatically restarted when the input signal disappears from what channel.



Blinks also when scanning is stopped

The above condition indicates that scanning is about to restart because there is no longer a signal on the channel.

 If the PTT button on the microphone is depressed once to put the transceiver into the transmission mode, scanning is not restarted when the found signal disappears.



Stops blinking

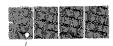
- c. To search for vacant channels:
 - * Set the MODE selector on the front panel of the unit to the VACANT position.
 - Adjust the SQUELCH control to eliminate FM noise.
 - Scanning is automatically stopped at a frequency on which there is no signal.
 - Scanning is restarted when a signal appears on the previously vacant channel.



Blinks also when scanning is stopped

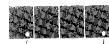
The above condition indicates that scanning is about to be restarted because a signal has appeared on that channel.

* If the PTT button on the microphone is depressed to put the transceiver into the transmission mode, scanning is not restarted even if a signal is present on the channel.



Stops blinking

- d. To scan continuously:
 - * Set the SCAN MODE switch to the FREE position.
 - Adjust the SQUELCH control to eliminate FM interstation noise.
 - Scanning will be started at an interval of 0.25 or 2.0 seconds regardless of the presence or absence of signals.
- e. To suspend scanning operation:
 - * Press the CCL button on the front panel of the unit.
 - * Or press the PTT button on the microphone once to put the transceiver into the transmission mode.
- B. How to scan the five frequencies stored in the mem-
- a. Press the <u>MEMO</u> button on the front panel of the unit. This will start scanning of frequencies sequentially the one stored in M1 through to the one stored in M5.



Blinks during scanning

Memory scan indicator: lights during scanning

When frequency data are stored in all the five memories:

Scan



* When M4 and M5 are vacant:

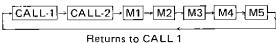
Scan



b. How to scan CALL frequencies together with memory frequencies:

Press the **CALL** button then the **MEMO** button. When all the memories are occupied, the scanning sequence is as shown in the following figure:





c. To search for a busy memory channel, or vacant memory channel, or perform continuous memory channel scanning, select the corresponding positions of the SCAN MODE switch on the front panel of the unit in the same way as for entire frequency band scanning.

(9) SELECTING CALL FREQUENCIES (145.50 MHz or 145.55 MHz)

a. A single depression of the CALL button selects call frequency 145.50 MHz, the one with the highest priority. Another depression of this button selects the other call frequency of 145.55 MHz. A third depression of the CALL button selects 145.50 MHz. Whenever the CALL button is depressed to select a call frequency, the call indication c is displayed after the frequency.

1st depression



Call channel indication



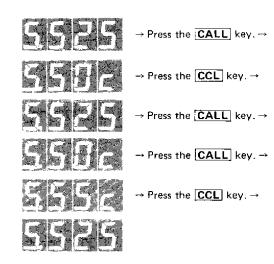


b. When a call channel is selected, all other key operations are ineffective except for the MEMO key or when the CCL key is depressed to reset the call function. When the call function is reset by depressing the CCL key, the channel frequency returns to the one displayed immediately before the CALL button was depressed.

When the MEMO key is depressed while a call channel is selected, memory and call frequencies are sequentially scanned in accordance with the selected position of the SCAN MODE switch.

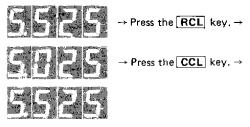
(10) OTHER USEFUL OPERATIONS

a. By using the CALL and CCL keys, the two call channels and one other channel can be easily obtained. (E.g.): When a frequency of 145.525 MHz is selected with the CHANNEL selector or UP-DOWN control:



b. By using the RCL and CCL keys, the frequency stored in memory M1 and another frequency can be easily obtained.

(E.g.): When the frequency 145.025 MHz is stored in M1 and another frequency (145.525 MHz) is selected with the CHANNEL selector or UP-DOWN control:



- c. During ALL or MEMO scanning, pressing the PTT (Press-To-Talk) switch on the microphone suspends scanning. By utilizing this feature, scanning can be stopped just by momentarily pressing the PTT switch on the microphone when the desired frequency is reached or desired QSO station is found while scanning.
- d. Step by step channel scanning can be made with the UP-DOWN control on the hand microphone.

5.3 RECEPTION PROCEDURE

- Pressing the PUSH ON/VOL switch (3) on the front panel of the unit turns the power to the unit ON. When the memory is not backed up, the initial channel selection is always started at 145.00 MHz.
- Adjust the VOL control (3) to a comfortable loudness level.
- Set the SENS control (1) to a position which best suits object signal strength.
- Adjust the SQL control (2) so that FM white noise disappears when there is no input signal received.
- 5. Select the desired frequency as follows:
 - Select with the CHANNEL selector (5) on the front panel.
 - b. Select with the UP-DOWN control (29) on the microphone.
 - Press the CALL button to call on either 145.50 MHz or 145.55 MHz.
 - d. Press the SCAN ALL button to scan all frequencies. At this time, the following functions are available with SCAN MODE switch operation:
 - * BUSY: stops scanning at a busy channel.
 - * VACANT: stops scanning at a vacant channel.
 - * FREE: scans all frequencies to check band condi-

tion. Two scanning speeds are selectable with the SCAN SPEED switch (15) on the front panel of the unit. Also, scanning interval of either 5 kHz or 25 kHz is selectable with the SCAN STEP switch on the rear of the unit.

e. Press the SCAN MEMO button (12) to scan the frequencies stored in the memories.

At this time, the following functions are available with SCAN MODE selector operation:

- * Same as those obtained in SCAN ALL mode (with SCAN MODE and SCAN SPEED selector functions).
- f. Press the MEMO RCL button (8) to recall frequencies stored in the memories.

For details of the above procedure, refer back to section 2) "Microcomputer Operation".

6. The receiver section of the C8800 is designed for such ultra-high sensitivity that the reception in the DX position can be affected by intermodulation. To obtain maximum reception performance from your transceiver, select the optimum sensitivity with the SENS control from among the following three positions:

DX: for DX communication NOR: for normal communication

LOC: for situations where reception is affected by severe interference.

5.4 TRANSMISSION PROCEDURE .

- 1. Prior to transmission, make sure that your transmission frequency does not interfere with other commu-
- Select transmission power of LOW or HI with the PWR selector (4) on the front panel of the unit. For local communication, LOW is recommended.
- 3. Press the PTT (30) button on the Hand Microphone to put the transceiver into the transmission mode. Talk into the microphone from a distance of 5 to 10 cm.

5.5 DETERMINING X'TAL FREQUENCY FOR REPEATER-3

1. How to determine X'tal frequency:

The basic equation for PLL frequencies is:

$$fc = freq \times N + f_L$$

where fc: Lowest carrier frequency (144.00 MHz)

freq: Reference frequency (5 kHz)

Minimum number of Programable Divider (1200)

PLL local frequency

(E.g. 1): To shift transmission frequency 1 MHz higher:

= 139 MHz

Therefore, the desired X'tal frequency is:

$$\frac{f_L}{3} = \frac{139 \text{ MHz}}{3} = 46.333333 \text{ MHz}$$

(E.g. 2): To shift transmission frequency 1 MHz lower:

= 137 MHz

Therefore, the desired X'tal frequency is

$$\frac{f_L}{3} = \frac{137 \text{ MHz}}{3} = 45.666666 \text{ MHz}$$

2. Specifications of X'tals

Overtone X'tal Type 25U

For frequency deviations, see the following table.

Temperature	Frequency deviation
25°C	±20 PPM
-10°C ~ +50°C	±10 PPM

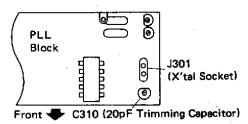
- 3. X'tal installation and adjustment
 - a. With the front panel of the unit facing forward, remove the top lid.
 - b. Now you will see a shielded box, which contains the PLL block, at the front of the unit. Remove the lid from the box.
 - The socket (J301) to accommodate the X'tal for Repeater-3 is located to the right of the PLL shielded box (see the following figure). Install the X'tal of the desired frequency into this socket (J301).
 - d. Next, adjust the frequency.

A frequency counter capable of covering the transmission frequency band (140 MHz band) is required for frequency adjustment.

First, set the PWR selector on the front of the unit to LOW, then make the necessary connections to allow transmission frequency counting.

Using the CHANNEL selector or UP-DOWN control, set the channel frequency to 145.00 MHz, then press the RPT key to select Repeater-3.

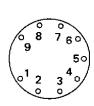
Put the transceiver into the transmission mode, and adjust the trimming capacitor (C310: 20 pF) so that the desired frequency shift is obtained in the frequency counter readout (E.g. The counter readout will be 146.00 MHz for upward shift of 1 MHz.)



When the transceiver is operated in the Repeater-3 mode, the transmission frequency is not displayed on the frequency readout. Exercise the utmost care at such times to avoid straying out of the amateur band.

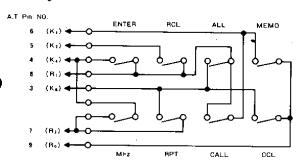
5.6 ACCESSORY TERMINALS

1. The pin configuration of the accessory terminal on the rear of the unit is as follows:



_ 1	GND											
2_	EX	T BACK UP										
3	K8											
4	K4]										
_5	K2]										
6	K1	For Key Board										
7	R2											
8	R1]										
9	RO]										

2. For remote control keyboard, use the following circuit configuration:



5.7 ADJUSTING PIEZO-ELECTRIC BUZZER SOUND LEVEL

The piezo-electric buzzer is fixed on the bottom cover (speaker side). The sound adjustment variable resister is located adjacent to the piezo-electric buzzer connector. Remove four screws from the bottom cover, lift the cover, then adjust the sound level using a slot driver.

5.8 RESETTING THE MICROCOMPUTER

In the event of a malfunction, or when key operation is not effective, reset the microcomputer in the following way:

- Turn the unit power switch and back-up switch located at the rear side, OFF. (The battery and power supply may be kept connected.)
- After about 5 seconds, turn the power switch and the back-up switch, ON.

SERVICE MANUAL SECTION

6. FUNCTIONS

6.1 RECEIVER SECTION

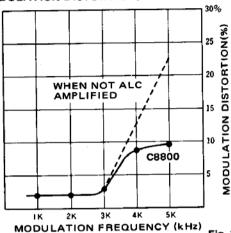
- * The reciever is a double conversion super-heterodyne device with the 1st IF at 10.7 MHz and the 2nd IF at 455 kHz.
- Incomming signals to the antenna terminals (J802) pass through an antenna switching circuit within the transmission booster (PB01) to JR01 of the RF pre amp (PR01).
- RF pre amp. outputs are MOS FET amplified in the RF main amp. (QR01).
- Sensitivity adjustments
 - DX position: Employs 2-stage RF amplification, RF pre amp. (QQ01) and RF main amp. (QR01).
 - NOR-LOC position: By means of 2 PIN diode switches (QQ02 and QQ03), RF pre amp. (QQ01) is deactivated and only RF main amp. functions.
 - Sensitivity for each position is preset by application of positive voltages to the FET gate 1 of the RF main amp. (QR01).
- QR01 outputs pass through a 3-stage helical cavity and are fed to gate 1 of 1st mixer QR04 (MOS-FET). Local signals from PLL (PL01), board J125-1, are fed through LR02 to gate 2. (Local signals: 133.3~135.3 MHz)
- * Signals converted to 10.7 MHz by QR04 pass through monolithic crystal filters (FR01 and FR05) thereby improving the set selectivity, intermodulation suppression, etc.
- Signals that have passed through the crystal filters are amplified by 1st IF amp. (QR05), and fed to 2nd mixer (QR06).
- * QR07 is the 2nd local oscillator.
- 10.7 MHz fed to QR06 is converted for 2nd IF, 455 kHz, and is fed to ceramic filters (FR03 and FR04).
- * Signals from the ceramic filters are amplified by QR09 and QR10, and then ratio detected. Detection outputs pass through the de-emphasis circuit, and are amplified by AF pre amp. (QR13).
- * Signals amplified by QR13 and QR20 drive speakers.
- The squelch circuit amplifies QR10 outputs (noises). Its outputs, pass through a L-C filter circuit and amplified by a 2-stage noise amplifier comprising QR15 and QR16. These signals are then diode rectified to provide DC voltages.
- Diode rectified DC voltages are fed to the base of QR19.
- * The QR19 collector is connected to the base of QR13 AF amp., to provide squelching functions. Also QR13 base currents are used to switch QR14 to provide scan control signals.

6.2 TRANSMITTER SECTION

- Signals from external microphones (MP716) amplified by Q401 and Q402, are rolled off above 3 kHz by a roll-off filter, and fed to C172 of the VCO circuit, to direct frequency module the VCO by reactance modulation.
- PLL board outputs are supplied to #2 pin of JT01 of the transmitter younger stage board (PT01).
- * Signals supplied from the PLL board are amplified sequentially by QT01, QT02, QT03, and QT04, and via #1 pin of JT02 fed to #1 pin of JB01 of the TX booster (PB01).
- QT01 and QT02 operate under a 9 V line voltage, but +B of QT03 and QT04 are regulated by the APC circuit (JT02 #3 pin).
- Signals fed to #1 pin of JB01 are power amplified by QB01 to approximately 20 W.

- Signals amplified by QB01 pass through a 3-stage low bandpass filter to the antenna terminals.
- QB01 is regulated by the +B line voltage of the APC circuit, so that the high & low power outputs can be trimmer adjusted within the PC01 board.

[C8800 MODULATION DISTORTION]



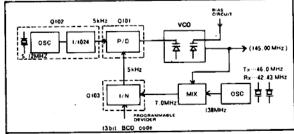
6.2.1 APC (Automatic Power Control)

- This circuit controls high and low power levels and automatically reduces RF outputs when SWR varies.
 It also maintains constant RF power during supply voltage fluctuations.
- This APC board (PC01) is controlled by the DC voltage supplied by the SWR detector within booster board (PB01).
- Progressive wave components are applied to QC03 and reflective wave components to QC04.
- As each source for QC03 and QC04 is compulsorily biased, base voltage variations in QC03 and QC04 are more likely to be reflected on the collector side.
- When, for instance, the supply voltage rises, or SWR deteriorates, the progressive or reflective wave level increases and reduces the QC03 and QC04 collector voltages.
- When the QC03 and QC04 voltages are reduced, the QC02 emitter voltage decreases, and QC01 (transistor) approaches a cut off state. This causes a reduction in the Q806 emitter current.
- Reduction in the Q806 emitter current limits the current in QT03 and QT04 in younger board (PT01) and QB01 of the booster, thereby reducing the RF power.

6.3 PLL SECTION

The PLL block used for C8800 has its PLL controlled by a 13-bit BCD code generated in the microcomputer section. In transmission mode it's outputs directly generate the frequencies required. In receiving mode, they generate frequencies 10.7 MHz below those required.

(Example) PLL circuit frequency relations in a 145.000 MHz transmission mode.



6.3.1 PLL IC

This PLL IC comprises:

A 13-bit BCD coded command from microcomputers (QL01 and QL02) is applied, determining the count down ratio. Frequencies from the mixer are devided by this ratio, and applied to the phase detector circuit.

(1) Programmable counter section (Q103)

A 13-bit BCD coded command from the microcomputer (QL02) is applied, determining the count down ratio. Frequencies from the mixer are divided by the ratio, and applied to the phase detector circuit.

_		-							_									
	DIS- PLAYED FREQ.		Q103(7C9122P) PIN NO.												COUNT DOWN RATIO			
ı	(MHz)	15	14	13	12	11	10	9	8	7	6	5	4	3	(N)			
1	144.000	1	0	0	1	0	0	0	0	0	0	0	0	D	1200			
ı	144.005	1	0	0	1	٥	0	0	0	0	0	0	0	1	1201			
\	144.010	1	0	0	1	0	0	0	0	0	0	0	1	0	1202			
7	144.015	1	0	0	1	0	0	0	0	0	0	1	1	1	1203			
ľ	144.020	1	0	0	1	0	0	0	0	0	0	0	0	0	1204			
1	·-·:														:			
ı	144.100	1	0	0	1	0	0	0	1	0	0	Ð	0	0	1220			
ı	;	•	· ·															
ı	144.500	1	0	0	1	1	0	0	0	0	D _.	D	0	0	1300			
					i										;			
1	145.000	1	0	1	1	1	1	0	0	0	0	0	0	0	0	0	0	1400
ľ	: : :														<u>:</u>			
ı	145.240	1	0	1	0	Ö	O	1	0	0	1	0	0	D	1448			
-	:																	
	145,500	1	D	1	0	1	0	0	0	0	0	0	0	0	1500			
Γ	:														[: "			
	145,995	1	D	1	0	1	1	0	0	1	1	0	0	1	1599			
[,											
Γ	N	1		5	5			!	9			9						

Count down ratio (N) computation formula:

(Desired frequency in kHz - 138,000 kHz) \div 5 = count down ratio

(Example) If 145.000 MHz is desired:

 $(145,000 - 138,000) \div 5 = 7,000$

7,000 ÷ 5 = 1.400

(counter down ratio)

(2) Phase detector circuit (P/D cct.) (Q101)

- Detects phase differences between 5 kHz which is 1/1,024 of the reference oscillator frequency (5.12 MHz), and the frequencies from programmable counter.
- 2) This circuit varies VCO circuits oscillating frequencies by obtaining detected signals from #3 pin, and converting them to DC voltages through an integrating circuit comprising C's and R's, and varying the voltages applied to varicaps (varactors).

6.3.2 VCO circuit (P150)

- Outputs from P/D cct, of Q101 PLL IC are converted to DC voltages via an integrating circuit comprising C's and R's.
- (2) Variations in these DC voltages are fed to the Q151 varicap diodes, to alter varicap capacitances.
- (3) By capacitance variations in varicap diodes, the VCO circuit oscillating frequencies are controlled,
- (4) Depending on DC voltage variations, a maximum frequency variation of approximately 14 MHz can be

provided,

6.3.3 Local oscillator section (local OSC)

- The local OSC section provides by overtone oscillation 127.3 MHz for RX and 138.0 MHz for TX.
- 2) This signal is applied to the mixer section of Q202,

6.3.4 Mixer section (Mix, Q201 and Q202)

- Signals from VCO are picked up after passing through Q120 and Q121, and applied to the mixer section through Q201 the buffer amp.
- (2) In the mixer section, signals from VCO and local OSC are mixed, providing signals of 6.0 to 7,995 MHz.

 $F(Vco) - F(local) = 6.0 \sim 7.995 MHz$

- (3) Signals from the mixer section, after passing through LPF, are amplified by Q203 and Q204 and applied to the 1/N circuit of PLL IC (Q103).
- (4) Pt.L IC Unlock Extracts lock and unlock signals from phase detector circuit.

6.3.5 Unlock switch circuit (UL, Q104)

Depending on PLL IC and UL output conditions, UL and lock modes are judged by Q104.

- (1) Signals to be applied to 1/N circuit are frequency devided at a predetermined count down ratio, and signals thus devided are fed to the phase detector circuit via the 1/N circuit,
- (2) Until reference signals and 1/N circuit signals coincide within the phase detector circuit, repeated controls are exercised within the Fig. 2 loop.
- (3) When reference and 1/N circuit signals coincide, it is called a locked state.

6.4 CONTROLLER SECTION

Consists of the following sections:

PL01: Microcomputer section

PD01: Display section

PD01: Channel selector section (manual)

PM01: Control I/O decoder section

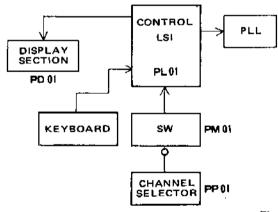


Fig. 3

Re control LSIs QL01, and QL02
 These MOS LSIs function with a power supply in a range of +8V to +10V. It is 9V in C8800.

6.4.1 To control external circuits, the following outputs are provided:

- PLL IC programmable counter drive
 13-bit BCD coded outputs for driving programmable counter are provided at pins #7 ~ 18 of QL02 and #2 pin of QL01, a total of 13 terminals.
- (2) 7-segment LED drive Signals from pins #10 ~ 17 and #20 ~ 24 of QL01 drive a 4-digit 7-segment LED.

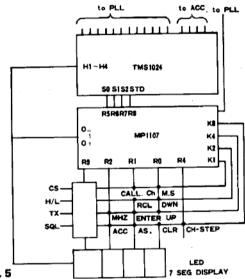
(3) Feature section for repeater mode selection By punching RPT on keyboard, outputs as per Fig. 4 are provided at pins #19(A7), #20(B7), #21(C7), and #22(D7).

	A 7	B7	C7	D7
s	1	0	0	0
R 1	0	1	0	0
R 2	0	0	1	0
R 3	0	0	0	1

Fig. 4

6.4.2 To operate LSIs, the following commands are applied to terminals indicated:

- (1) Initial clear (INIT, pin #9)
 - When turning power on, a positive pulse is applied to pin #9 to clear all in LSIs.
- (2) Matrix circuit (pins #21 (R0) ~ #24 (R3) and #5 (K1) ~ #8 (K8))
 - By using this matrix circuit, 16 key inputs are feasible.



- Fig. 5
- * Selection by channel knob (manual)
 - a. Channel selection commands to microcomputer are delivered by photo-interruptors QP01 and QP02.
 - b. The two photointerruptor signals are so segregated by UP-DOWN discriminator circuits (QM03 and QM04) within PM01 as to divide channel number variations into UP key and DOWN key. When the channel knob is turned an equal number of pulses to the channel number variations are applied to UP key.
 - Divided signals are fed from QM05 to analog switch QL06 via JM04.
 - d. By applying a high level voltage to the #13 control terminal of QL06 for UP and #12 for DOWN, terminals R0 and K4 for UP, and R0 and K2 for DOWN, are short circuited through a resistance of approximately 260 ohms in value.
 - e. In short, by segregating into UP and DOWN, the analog switch in QL06 is turned on, closing the matrix.
- * Selection by microphone switch
 - In UP-DOWN control by rotary switch, the analog switch is turned on and off by pulse.
 - In UP-DOWN control by microphone switch, the analog switch is turned on and off by DC.
 - UP-DOWN commands from microphone are applied to #5 and #6 of QL06.

[CHANNEL SELECTOR STRUCTURAL DIAGRAM]

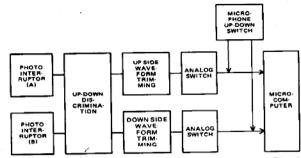


Fig. 6

- 1) Channel selection
 - Matrix circuits are closed between R0 and K2 for UP, and between R0 and K2 for DOWN.
- Memory enter (MEMO-ENTER)
 Matrix circuit between R1 and K4 is closed.
 Its function is to memorize the frequency being displayed.
- 3) Memory recall (MEMO-RCL)

 Matrix circuit between R1 and K2 is closed.

 Its function is to recall the frequency in memory

 Memory recall the frequency in memory.

 Memory recall the frequency in memory.
- Scan all (SCAN-ALL)
 Matrix circuit between R1 and K8 is closed.

 Its function is to have scanning started from the channel displayed in the UP direction.
- Scan memory (SCAN-MEMO)
 Matrix circuit between R1 and K1 is closed.
 Its function is to have the 5 channels in memory
- sequentially scanned.
 6) Repeater (RPT)
- Matrix circuit between R2 and K8 is closed.
 Its function is to change A7 D7 codes from S to R1 to R2 to R3 to S, in this sequence.
- Call channel (CALL CH)
 Matrix circuit between R1 and K1 is closed.

 Its function is:
 - to call 145,50 at the initial switch on to call 145,55 at the second switch on to call 145,50 at the third switch on
 - and to repeat this process.
- 8) CCL
 - Matrix circuit between R0 and K8 is closed. Its function is to cancel all of MEMO RCL, SCAN ALL, SCAN MEMO, and CALL CH.
- 9) MHz
 - Matrix circuit between R2 and K4 is closed.
 Its function is to change just MHz order numerals.
 Example: 145.025 to 144.025 to 145.025
- 10) Scan speed selection
 - a. Matrix circuit between R3 and K2 is closed.
 - By scan speed switch (SM02) on front panel, the analog switch of QL07 is turned on or off.
 - When the analog switch is on, the scan speed is low: 0.5 channels per second.
 - d. When the analog switch is off, the scan speed is high: 4 channels per second.
- 11) Scan mode selection (Busy, Auto, Vacant)
 - a. In busy position, scanning stops when a signal is received.
 - b. When a signal is received, low level is output from the QR14 collector.
 - Low level from QR14 collector is applied to QM02 which inverts it and provides high level output.
 - d. Output from QM02 is applied to the analog switch QL07 and QL07 closes the matrix circuit between R3 and K8.
 - In vacant position, scanning ceases when no signal is received.

- f. For no signal, high level output is provided on QR14 collector.
- g. High level signals from the QR14 collector are applied to QM02, cycled twice, to provide high
- h. Output from QM02 is applied to analog switch QL07 and closes the matrix circuit between R3
- 12) Re: control section in transmission mode
 - a. While transmitting the matrix circuit between R3 and K4 should be closed, nullifying all inputs, to insure no IC environmented variation.
 - b. Analog switch QL07 is turned on and off by transmission at +B.
- 13) Re: selection between 5 kHz and 25 kHz
 - a. Rear panel slide switch S803 selects: S803 off ≈ 5 kHz separation C803 on = 25 kHz separation
 - b. Matrix circuit between O7 and K1 is closed.
- 14) Chip select switch (CS)
 - a. Matrix circuit between R3 and K1 is closed.
 - b. The chip select switch is ganged with the power switch.
 - c. Switching to +B turns analog switch QL107 on. Analog switch on: Normal operation

Analog switch off: Stops controller tions and turns display off. However, the memory section continues to function.

[5.50C FIRING PRINCIPLE]

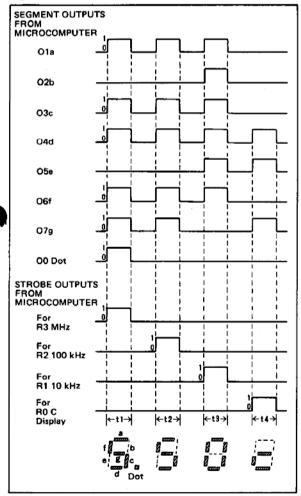


Fig.7

6.4.3 Display section

- LSI QL01 segment outputs are driven by segment drive IC's QL04 and QL05, and QL03 dynamically drives a 4-digit 7-segment LED.
- Levels when 145,50C is displayed are shown in Fig. 7.
- Per the above, Fig. 7 signals are repeatedly applied to O0-O7 terminals, firing each segment.
- In synchronization with QL01 segment outputs, strobe signals from R0--R3 are applied to QL02 (digit driver).
- QL02 displays 4 digits QD01-QD04.
- Close scrutiny of a dynamic drive reveals that digits are sequentially lit up, one digit at a time. However, due to fast cycles, all 4 digits appear to light up simultaneously.

6.4.4 Operation of CTN-5

The 1750 Hz tone signal is fed to Q101 emitter during transmission. This signal passes through the MIC input circuit and AF circuit, and is then fed to the modulator where it is modulated. The modulation degree can be adjusted with the output level control VR on CTN-5, In CW mode, Q101 is reverse biased, so the signal is not modulated,

6.4.5 Back-up unit

- (1) With QZ04 (zener) as reference voltage, lowering of the base and emitter voltages in QZ01 turns QZ01
- QZ01 is used to turn on QZ02, and QZ02, QZ03, thereby driving the DC-DC converter (AZ01).

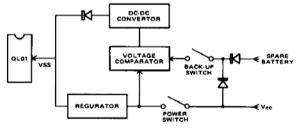


Fig. 8

- (3) AZ01 provides 10 V.
- This back-up unit operates when the power supply voltage is around 11 V, and maintains the power supply for MEMO circuits of QL01 at 9 V until it is reduced to 3 V.

6.4.6 Controller peripheral circuits and functions

- (1) QL03 (µPA47C) digit driver
 - Digits are lit up and switched by strobe signals (R0-R3) from QL01, and controller IC.
 - μPA57C is an integrated circuits of darlington connected NPN transistors and peripheral resistors.

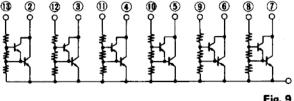


Fig. 9

(2) QL04 and QL05 (TA-76) segment drivers These are ICs for driving LEDs.

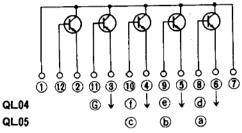


Fig. 10

(3) QL07 (14016CP)

- This IC is for analog switches, and in C8800 is used in QL06, QL07, QM01, and QM02.
- * As shown below, when a high level signal is applied to CONTROL, IN and OUT turn on.

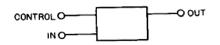
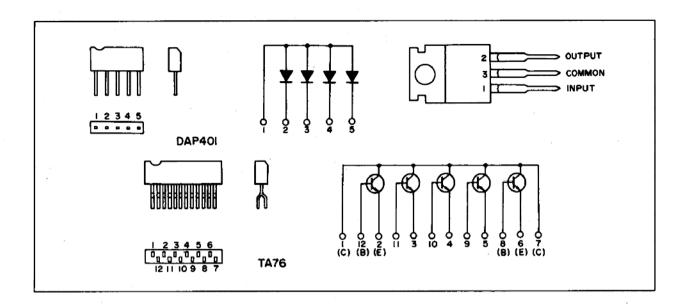
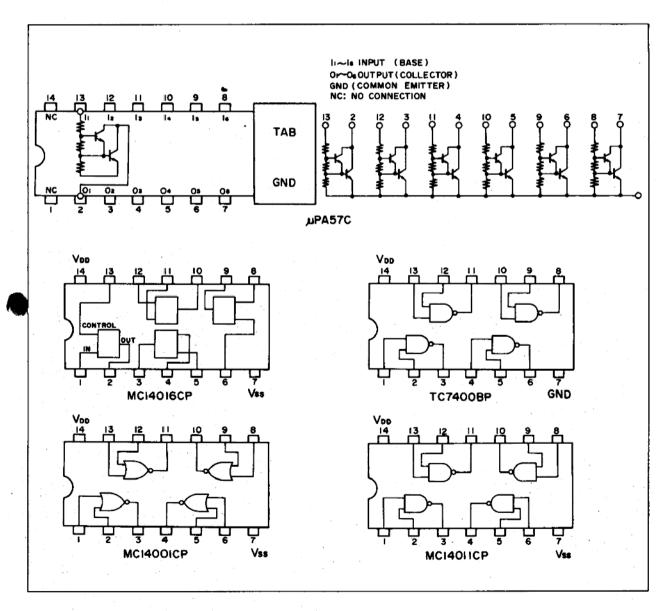


Fig. 11

6.4.7 Trouble shooting

SYMPTOM	CAUSE	REMEDY					
No display	No voltage on each B line.	Check power supply circuit boad and connector contacts.					
	LSI clock generator not oscillating.	Check circuit parameters					
1	CS not on.	Check power supply circuit board and connector contacts.					
	No signal at output terminals to LED.	No voltage at +B for segment driver.					
	Miswiring.	Check wiring, or poor connector contacts.					
Irregular display	Low power supply voltage.	Correct to 13.8 V.					
	Power switched on and off in fast cycles.	Pull out power plug, replace after several seconds, and turn power on again.					
	Miswiring to individual segments.	Check wiring.					
	Shorted pattern at LED terminals.	Check pattern (circuit board).					
Punching keys do not provide	TX SW is on.	Check power supply block.					
proper functions	Keyboard miswiring.	Check wiring.					
	Connector poor contacts.	Check connector.					
Channel display remains UP-DOWN and other keys do not work.	UP-DOWN has turned analog switch on.	Check UP-DOWN circuit in feature block and repair.					
Display outside of band or	Miswiring.	Check wiring.					
wrong CH STEPS.	Power switched on and off in fast cycles.	Pull out power plug, replace after several seconds, and turn power on again.					

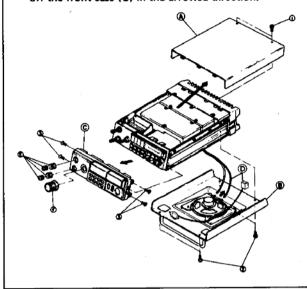




7. DISASSEMBLY

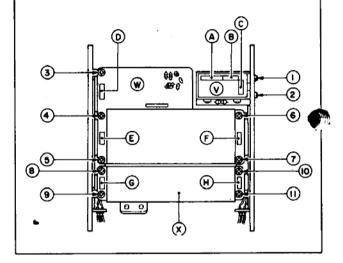
7.1 REMOVAL OF ESCUTCHEON

- 1. Remove 2 screws (1) and lift off top cover (A) in the arrowed direction.
- Remove 4 screws (2), then pull off speaker jacks and buzzer cord (D) in the arrowed direction, for loosening the bottom cover (B).
- Remove knobs (E) and (F), and 4 screws (3), then lift off the front case (C) in the arrowed direction.



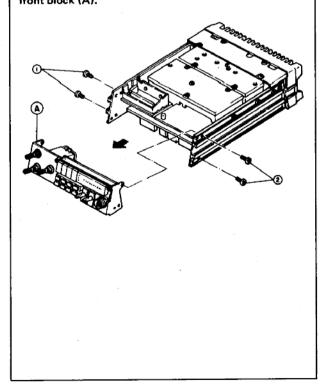
7.3 REMOVAL OF UPPER BOARDS

- Removal of board (V)
 Disconnect connectors (A), (B), and (C), remove 2
 and (2), to remove board (V).
- Removal of board (W)
 Disconnect connectors (D), (E), and (F), remove 5
 screws (3), (4), (5), (6), and (7) to remove board (W).
- Removal of board (X)
 Disconnect connectors (G) and (H), remove 4 screws (8), (9), (10), and (11) to remove board (X).



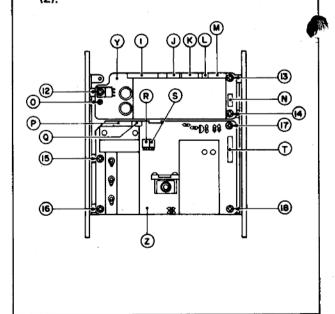
7.2 REMOVAL OF FRONT CONTROL SECTION

Remove 8 screws, 4 each (1) and (2), then disconnect connectors and desolder soldered joints, to loosen the front block (A).



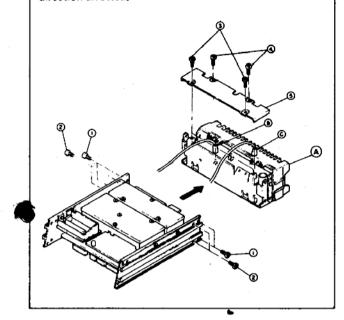
7.4 REMOVAL OF LOWER BOARDS

- Removal of board (Y)
 Disconnect connectors (I), (J), (K), (L), (M), and (N),
 pin jack (O), then remove 3 screws (12), (13), and
 (14), to remove board (Y).
- Removal of board (Z)
 Disconnect (P), (Q), (R), (S), and (T), remove 4
 screws (15), (16), (17), and (18), to remove board (7)



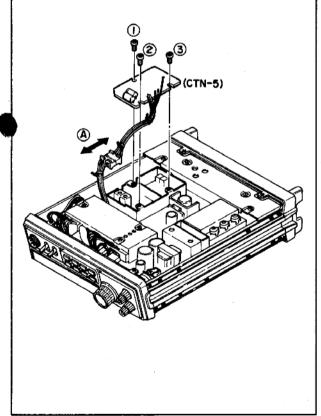
7.5 REMOVAL OF FINAL HEAT-SINK

Remove 8 screws, 2 each (1), (2), (3), and (4), shielding plate (5), disconnect connectors (B) and (C), desolder soldered joints, to remove final heat-sink (A) in the direction arrowed.



7.6 REMOVAL OF TONE BOARD (CTN-5)

Remove 3 screws (1), (2) and (3), then pull off connector (A) in the arrowed direction.



8. ADJUSTMENT PROCEDURES

STANDARD CONDITIONS

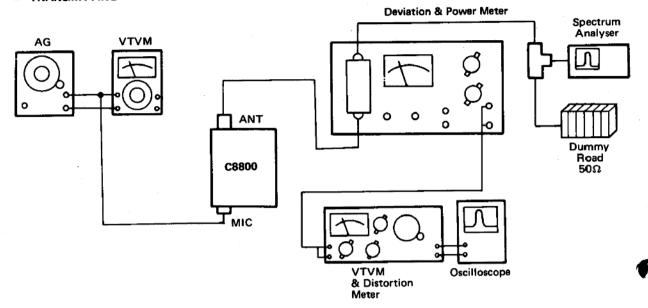
Power supply voltage.											13.8V DC
Receiver output											.500 mW
Receiver load											
Transmitter load											50 ohms
Modulation											1,000 Hz
Deviation											
Adjustment frequency						R	X	•	14	5	.500 MHz
											480 MHz

* Test equipment and jigs

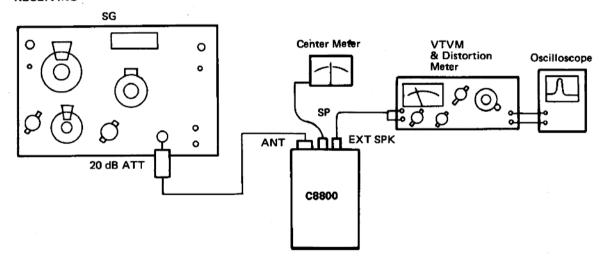
- (1) Frequency counter
- (2) RF millivoltmeter (VTVM)
- (3) 50-ohm dummy load for RF VTVM
- (4) Digital voltmeter
- (5) Circuit tester (preferrably with high input impedances)
- (6) Power supply (13.8V, 4A)
- (7) Transmitting jig (or microphone)
- (8) 2P Molex socket (coaxial with N type male)

TRANSMITTING AND RECEIVING CONNECTIONS

■ TRANSMITTING



■ RECEIVING



8.1 PLL ADJUSTMENTS (P101)

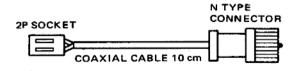
- When adjusting PLL and RX, keep PTT off unless otherwise specified.
- * Adjust PLL before RX and TX.
- PLL section is thoroughly factory adjusted, so that these trimmers require no further adjustment.
- While PLL related adjustments are being carried out, leave socket J125 disconnected. Replace the socket after adjustments are completed.

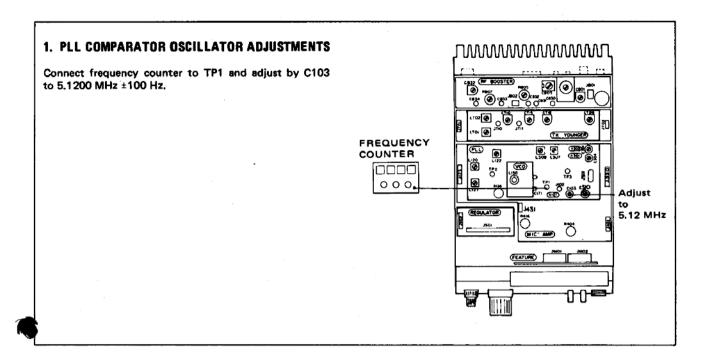
■ ADJUSTMENT CONDITIONS

- ~		,,	м.		•				44				v	••	•											
SENS.																										DX
SQL																										. MIN
PWR .																					•		•	•		ні
VOL .			-	•	-	-	_		-	-	-	-	-				-									
MODE		_	_	-	-	-	-	-	-	-	-															
SCAN.					-	-	_	-	_	-	-	-	-	-		-										
CH STE		-	-	-	-	_	_	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		_	
BUCK		-	_	-	-	_	-	-	-	-	-	-	-		-	-	_	_	-	-	_	-	-	-	-	
POWER	R S	UI	PP	Ł	Y	٠.	_	_		_		_					_	_	_	_		_	_	_	.1	13.8 V

JIGS

- 1) 2P molex socket
- 2) 50-ohm dummy load for RF VTVM N type supplied with RF VTVM is to be used.







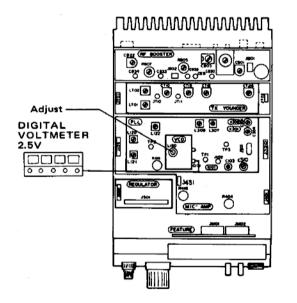
 Position cores of L307, L308, and L122 as shown below:



- 2. Adjust the above 3 coils as follows:
 - a. Screw in L307 1.5 tyrns.
 - b. Screw in L308 4.5 turns.
 - c. Screw in L122 1.0 turn.
- Adjust frequency display on unit to 145,000 MHz using the channel knob.
- Connect digital voltmeter to the feed-through capacitor C171 that is mounted on VCO.
- Then switch to the TX mode, and adjust the digital voltmeter to 3.0 V using VCO coil L150.
- Then switch to the RX mode (S), and adjust the digital voltmeter to 3.0 V using R136.

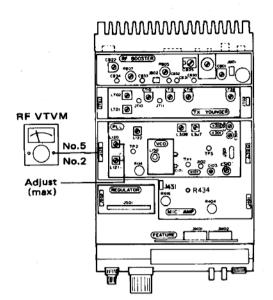
NOTE:

When using a circuit tester, use 10 V range or above for adjustments.



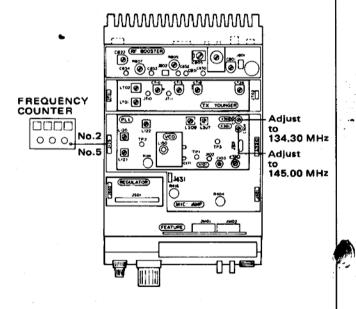
3. OUTPUT COIL ADJUSTMENTS

- 1. TX coil adjustment
 - a. Set the unit display at 145,50 MHz.
 - b. Connect to #5 pin of J125 an RF VTVM which has a 50-ohm load resistance.
 - Maximize the output at #5 pin of J125 by adjusting L120. (RF VTVM should indicate approximately 0.3 V)
- 2. RX coil adjustment
 - a. Display 145,50 MHz.
 - b. Connect to #2 pin of J125 an RF VTVM which has a 50-ohm load resistance.
 - Maximize the output at #2 pin of J125 by adjusting L121.



4. FREQUENCY ADJUSTMENTS

- 1. Turn channel knob to display 145.00 MHz.
- 2. Connect frequency counter to #2 pin of J125.
- Switch to the RX mode (where A1, A2, and A3 LEDs are off), and adjust C304 for the counter to indicate 134.40 MHz.
- 4. Then connect frequency counter to #5 pin of J125.
- Switch to the TX mode, and adjust C301 for a frequency 145.00 MHz at #5 pin.
- Stop transmitting, shift the channel to 144.00 MHz, transmit and make sure that the frequency is indicated by the channel display.
- 7. Similarly make sure on 145.98 MHz and 145.50 MHz.



The above completes PLL related adjustments, so that J125 socket can now be reconnected.

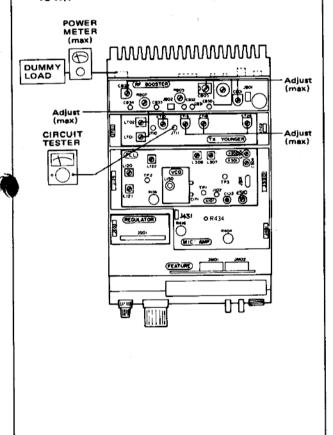
8.2 TX ADJUSTMENTS

1. YOUNGER BOOSTER PWR ADJUSTMENTS

(CO	NDITIONS)
1.	SENSDX
2.	SQL MIN
3.	PWR
4.	VOL
5.	MODE FREE
6.	SCANLOW
7.	CH STEP
8.	BUCK UPOFF
9.	Power supply
10.	Dummy load
	Frequency 145.48 MHz
12.	External UP-DOWN SW Center

(PROCEDURES)

- Using the channel selector knob, adjust to 145.48 MHz.
- Turn trimming resistors RC07, RC08, and RC12, of APC board to extreme left (minimum).
- 3. Maximize CB22 booster board capacitance.
- 4. Connect a tester to JT11 of the younger board.
- Switch to TX mode, and adjust a few times to maximize voltages at LT01, LT02, and CT10. (Should be approximately 0.26 V)
- Disconnect the circuit tester, and while watching the RF power meter, maximize RF power by adjusting a few times CT15, CT18, and CT26 of the younger board, and then CB01, CB05 of the booter board, in that sequence. (RF power should be approximately 18 W).



2. POWER PROTECTOR ADJUSTMENTS

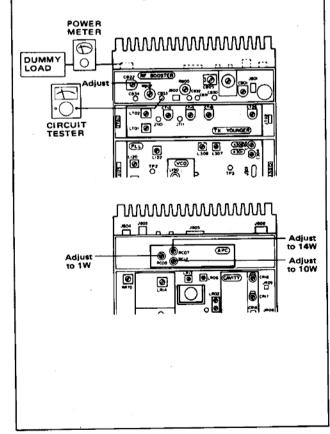
(COI	NDITIONS)
1.	SENSDX
2.	SQL
	PWR
4.	VOL
5.	MODE
6.	SCAN
7.	CH STEP
8.	BUCK UPOFF
9.	Power supply
10.	Dummy load
11.	Frequency 145.48 MHz
12.	External UP-DOWN SW Center

(PROCEDURES)

- Switch to high power TX mode, and connect a circuit tester to CB33 of the booster board. Adjust accurately to reach the dip point by RB07.
- Switch to low power, and set the RF power at 1 W by adjusting RC07 of the APC board.
- Switch to high power, and set the RF power at 14 W by adjusting RC08.
- Switch to the RX mode, Replace the ANT dummy load with the SWR-5 dummy load, and transmit at high power, By adjusting RC12, set the RF power at 10 W.
- Replace ANT dummy load with 50 ohms, and adjust RC07 and RC08 to obtain 14 W at high power and 1 W at low power.

NOTE:

When using SWR-5 dummy load, the total length of the coaxial cable from ANT connector to the dummy load should be $0.67 \times \lambda/2 \times \eta$, or 69 cm and 1,038 cm.



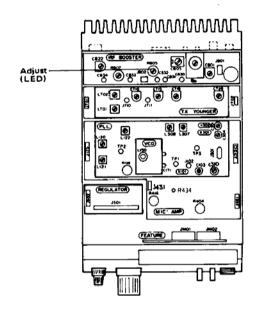
3. TX METER ADJUSTMENTS

	NDITIONS)
1.	SENSDX
2.	SQL
3.	PWR
4.	VOL
5.	MODE
6.	SCANLOW
7.	CH STEP
8.	BUCK UP OFF
9.	Power supply
10.	Dummy load
11.	Frequency
12.	External UP-DOWN SW Center

(PROCEDURES)

- Switch to high power TX mode, and by adjusting RB05 of the booster board, set at the point where the 9th LED (the 3rd red) is turned off.
- Switch to low power, and confirm that one of the first 4 LEDs turn on.

(1st through 4th for low power, and 7th through 9th for high power is OK).

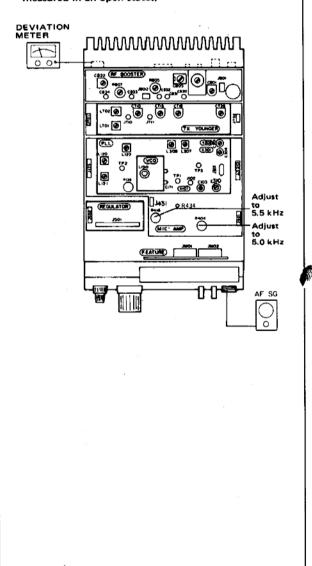


4. DEVIATION ADJUSTMENTS

,	NDITIONS)
1.	SENSDX
2.	SQL
3.	PWR
4.	VOL
5.	MODE
6.	SCAN
7.	CH STEP
8.	BUCK UPOFF
9.	Power source
10.	Dummy load
11.	Frequency 145.48 MHz
	External UP-DOWN SW Center

(PROCEDURES)

- Apply to the MIC input terminals a signal whose output at AG is approximately 1 kHz, 30 mV RMS. Then turn R404 of the PLL board to the extreme counterclockwise position (maximum gain).
- Switch to the TX mode, and by means of R416, set where the deviation is 5.5 kHz maximum.
- Using R404, set for a deviation of 5.0 kHz maximum.
 (At 3.5 kHz dev, MIC sensitivity = 0.7 4 mV as measured in an open state.)

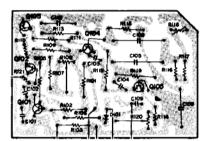


5. TONE UNIT & CTN-5 (tone oscillator for repeater drive) ADJUSTMENTS

	ONDITION													
1.	MODE									٠	٠			FM
2.	Band											1	44	MHz
3.	VFO											1	45	MHz
4.	PWR													MAX
5.	MIC input	t.												None

(PROCEDURES)

- Set the Push Tone Switch to ON (C8800 is set to transmit mode with signal modulated by CTN-5).
- 2. Turn R108 fully counterclockwise.
- 3. Adjust the modulation frequency to 1750 Hz by adjusting R118 on the P.W. board (the frequency counter indicates the output of the FM linear detector).
- Adjust R120 on the P.W. board to obtain 3.5 kHz deviation.



8.3 RX ADJUSTMENTS

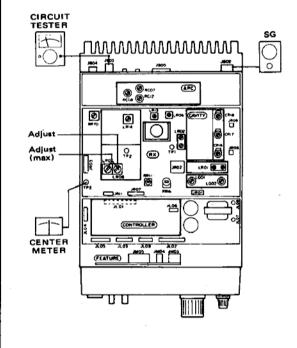
1. IF ADJUSTMENTS

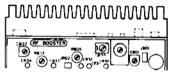
·----

(CO	NDITIONS)
1.	SENS
2.	SQL
3.	PWR
4.	VOL
5.	MODE
6.	SCAN
7.	CH STEP
8.	BUCK UP OFF
9.	Power source
10.	Dummy
11.	Frequency 145.50 MHz
12.	External Buck up SWOFF

(PROCEDURES)

- Set distortion meter or VTVM on a 1 V range, and maximize the noise level at SPK out by adjusting JR07 and LR08.
- 2. Connect center meter to TP3.
- 3. Apply a 60 dB unmodulated signal from SG.
- 4. Adjust LR08 for center meter to indicate: ±0.



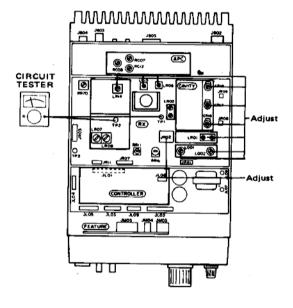


2. RF ADJUSTMENTS-PART 1

(CO	NDITIONS)
1.	SENSDX
2.	SQL
3.	PWR
4.	VOL
5.	MODE FREE
6.	SCANLOW
7.	CH STEP
8.	BUCK UP OFF
9.	Power source
10.	Dummy load 4 Ω
11.	Frequency 145.50 MHz
12.	External Ruck up SW

(PROCEDURES)

- Connect a circuit tester to TP1 of RX PWB. Maximize the voltage at TP1 by adjusting LR02. (Repeat this procedure a few times.)
- Connect a circuit tester to TP2, and apply a 60 dB unmodulated signal from SG. (A 0.1 V range.)
- Repeat adjustment a few times to maximize voltages at LR14, LR13, LR06, CR18, CR17, CR16, LR01, LQ02, and LQ01, in that sequence.



RF ADJUSTMENTS - PART 2: CAVITY

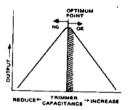
(CO	NDITIONS)
1.	SENSDX
2.	SQL
3.	PWR
4.	VOLMIN
5.	MODE FREF
6.	SCAN
7.	CH STEP
8.	BUCK UP OFF
9.	Power source
10,	Dummy load
11.	Frequency
12.	External Buck up SWOFF

(PROCEDURES)

NOTE:

Do not conduct these adjustments except when trimmers are replaced, or similar.

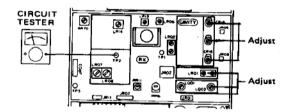
- 1. Connect a circuit tester to TP2 on the signal side.
- After adjusting per RF adjustments part 1, again adjust the cavity trimmers.
- Turn CR16 and CR18 by approximately 1 mm in the direction of increasing trimmer capacitance.
- By CR17, adjust to maximize the output at TP2, taking care to adjust to a point where, with output remaining at maximum, trimmer capacitances are slightly on the higher side.



NOTE:

Never adjust for trimmer capacitances to be the lower side of the optimum point,

- 5. Adjust CR16 and CR18 similarly to 4).
- 6. Adjust CR17 similarly to 4).
- Adjust LQ01, LQ02, and LR01 again to maximize the TP2 output,
- Repeat adjustments per 3) 6).
- Switch to normal, and adjust to 20 dB using RR16 and for 0 dB with QS.
- Switch RX sensitivity selector to local, and confirm that 20 dB QS is now 5 - 15 dB.
- Switch RX sensitivity selector to DX, and confirm that 20 dB QS is now above -7 dB.



NOTE:

The three trimmers in the RX cavity have been factory adjusted before shipment and no further adjustments are required. Never touch these trimmers.

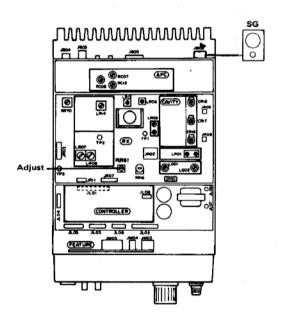
3. SQUELCH ADJUSTMENTS

(CONDITIONS)

1.	SENSDX
2.	SQL
3.	PWR
4.	VOL
5.	MODE
6.	SCAN
7.	CH STEP
8.	BUCK UPOFF
9.	Power source
10.	Dummy load 4 Ω
11.	Frequency 145.50 MHz
12	External Ruck up SW OFF

(PROCEDURES)

- 1. Turn squelch volume control to the maximum.
- Set SG for 1 kHz modulation at ±3.5 kHz deviation. Then set the SG attenuator to QS +5 dB.
- While applying the above SG output, adjust RR61 for squelch to open.
- Reduce the SG output for SQL to close, and reconfirm if it is accurately adjusted.
- Then set SG for 2.5 kHz modulation at ±4 kHz deviation. Increase SG output and confirm that double squelch does not occur.



NOTE:

Increase the SG output to bring down the opening point of squelch. Although the closing point of squelch varies about $1{\sim}3$ dB, tight squelch is obtained at the point at which the squelch opens with increased SG output.

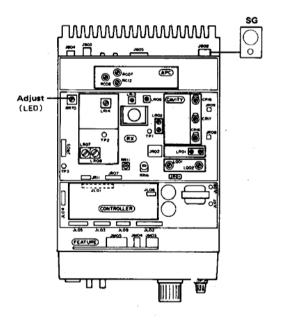
4. RX S METER ADJUSTMENTS

(CONDITIONS)

1.	SENSDX
2.	SQL MIN
3.	PWR
4.	VOL
5.	MODE
6.	SCANLOW
7.	CH STEP
8.	BUCK UPOFF
9.	Power source
10.	Dummy load 4 Ω
11.	Frequency 145,50 MHz
12.	External Buck up SWOFF

(PROCEDURES)

- Set SG for no modulation -13 dB, and adjust RR70 for one of S meter LEDs to light up.
- When varying SG output by SG attenuator, confirm that LEDs firing varies smoothly.
- When one LED is fixed at -13 dB, turn RR70 to the extreme counterclockwise position, measure S meter sensitivity (the point where one LED lights up), and confirm that it is within -10 dB to -16 dB.



5. CHIP SWITCH ADJUSTMENTS

(CONDITIONS) 1. SENS. .DX 2. SQL. MIN 3. PWR .HI 4. VOL. MIN 5. MODE FREE 6. SCAN. .LOW 7. CH STEP. .25 kHz 8. BUCK UP .OFF 9. Power source 9.5 V

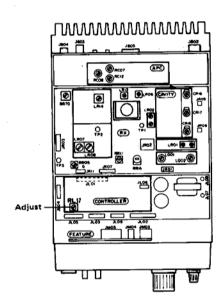
(PROCEDURES)

1. Set power supply voltage at 9.5 V.

NOTE

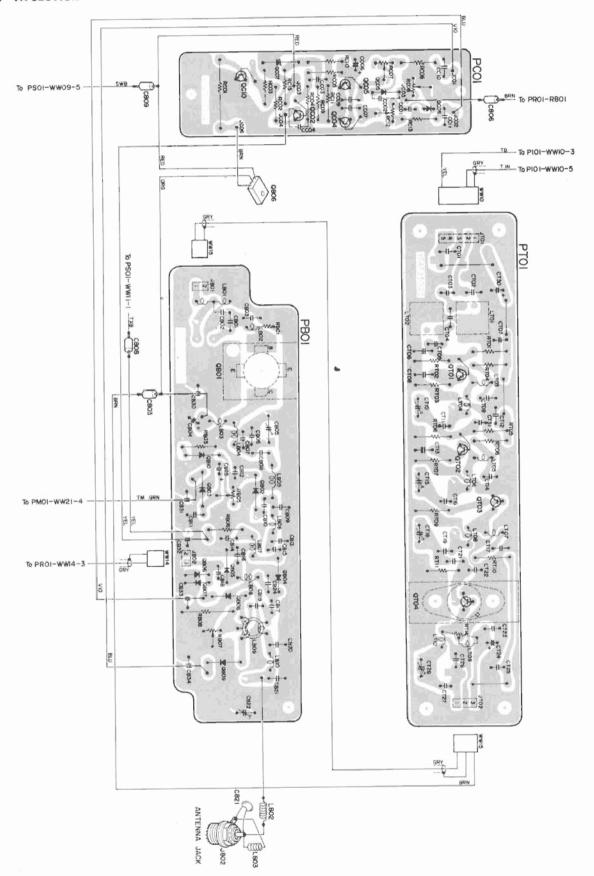
Use reliable equipment to get exactly 9.5 V.

- Adjust RL117 trimmer in the PL01 board for the frequency display to just disappear.
- Set power supply voltage at 13.8 V. Then reduce this voltage slowly and confirm that as it hits 9.5 V frequency the display disappear.

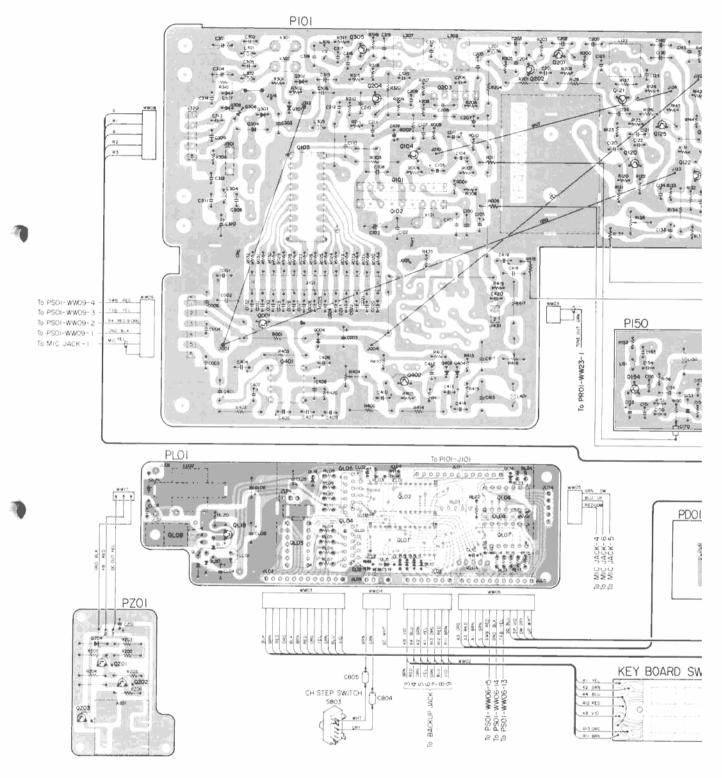


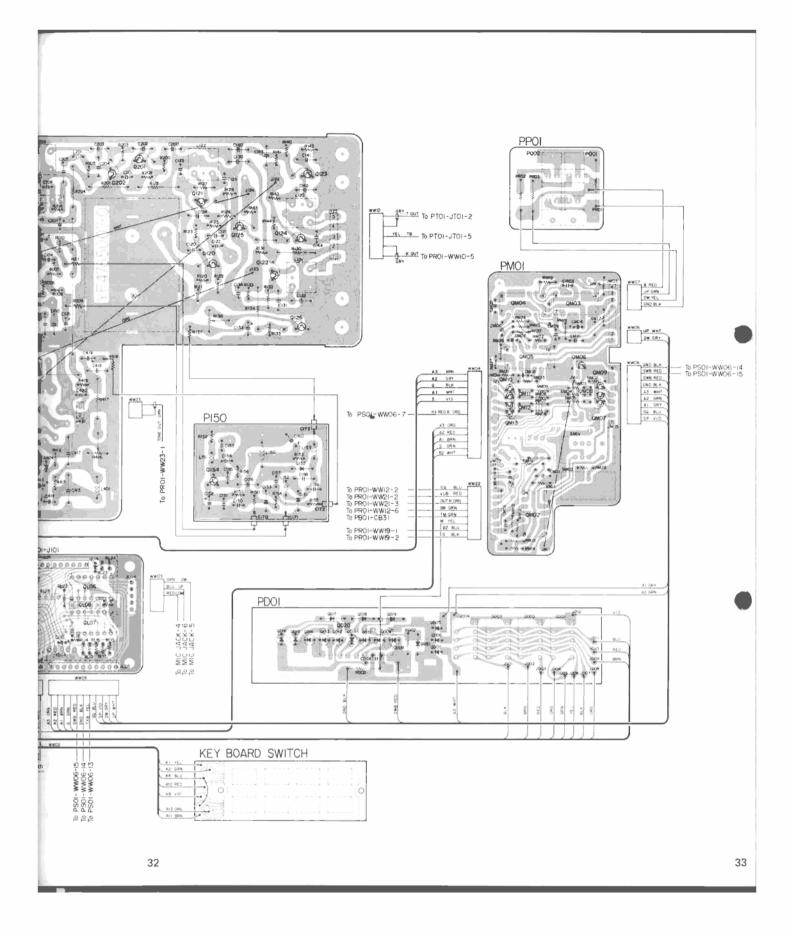
9. WIRING DIAGRAM

9.1 TX SECTION

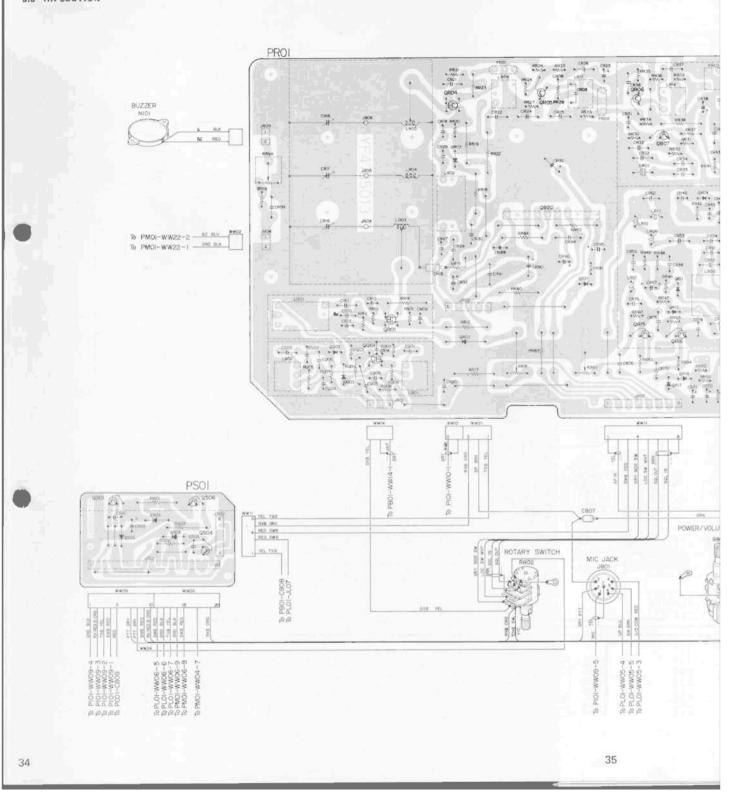


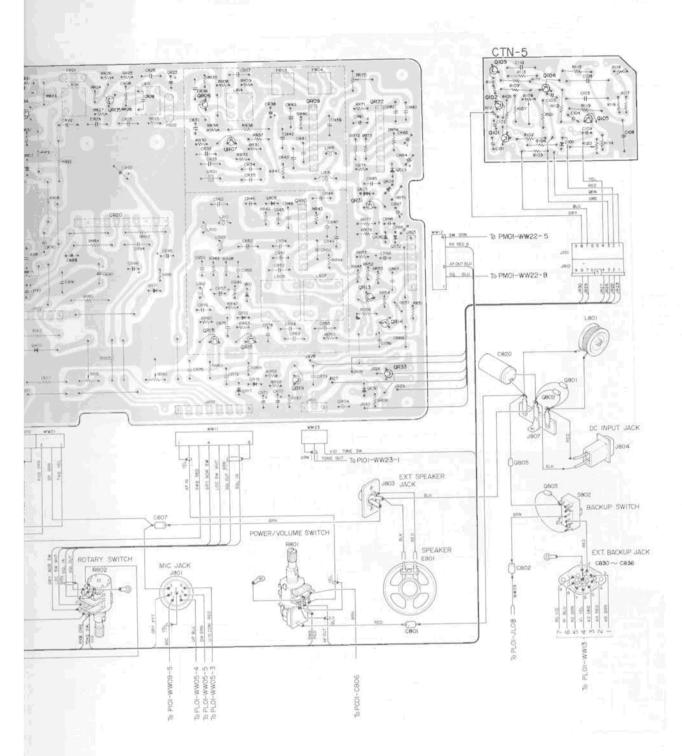
9.2 PLL SECTION



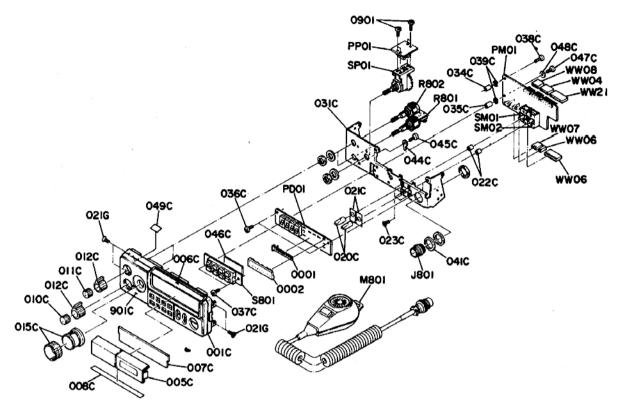


9.3 RX SECTION





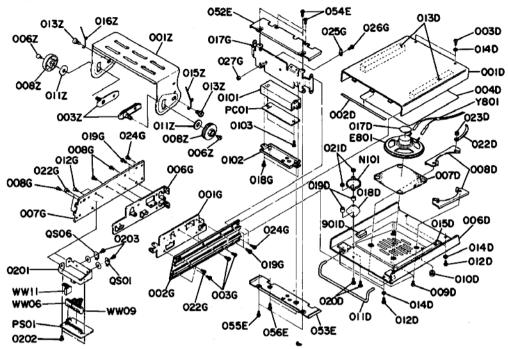
10. EXPLODED VIEWS AND PARTS LISTS 10.1 [P01-99] ESCUTCHEON RELATED



		QTY	PART NO.	
	DESIG.	.N	TARTINO.	DESCRIPTION
	A	1	4785064410	Front Case Assembly
	001C	1	4723064010	Front Case
	005C	1	4723158040	Window
	006C	1	4723303010	Mask
	007C	1	4723158020	Window
	008C	1	4723303020	Mask
	049C	1	4723120060	Insulator
1	901C	1	4723063030	Escutcheon, Front Panel
.	002C	1	59020604P0	Washer
П				
Ί	010C	1	4723154010	Knob, Volume
ı	011C	1	4723154020	Knob, SQL
1	01 2C	2	4785154010	Knob, SENS/PWR
ı	015C	1	4723154500	Knob, Rotary
1	020C	2	4723354010	Lever
ı	021C	2	4723118030	Spacer
J	022C	2 2 2 2	4723118060	Spacer
1	023C	2	51042604B0	F.H.M. Screw F2.6 x 4
1	031C	1	4723105010	Chassis, Front
1	034C	1	4723101010	Support
ı				
ı	035C	1	4723101030	Support
ı	036C	2	51102605B0	B.H.M. Screw B2.6 x 5
1	037C	2	4723114020	Stopper
ı	038C	1	50062605B0	Screw 2.6 x 5
ı	039C	2	54042602N0	Spring Washer
1	041C	1	4656118010	Spacer
ı	044C	1 [62030049W0	Lug
ı	045C	1	51100304B9	B.H.M. Screw B3 x 4
1	046C	1	4723120050	Insulator
ı	047C	1	51100208B0	B.H.M. Screw B2 x 8
ı	048C	1	59020605P0	Washer
ı		- 1		
_				

REF. QT		PART NO.	DESCRIPTION				
DESIG.	N	1201	DESCRIPTION				
l							
021G	4	51042605E0	F.H.M. Screw F2.6 x 5				
0901	1 4	51060308B9	F.H.M. Screw F2.6 x 5 P.H.M. Screw B3 x 8				
	`.,	0.0000000	1 SCIEW B3 X 8				
M801	1	MP11000692	Microphone, MP716				
2001	1	4785303010	Mask				
2002	1	4785053010	Cover				
J801	1 1	YJ10001250	Jack, Mic (7P)				
R801	1	RD12030070	Variable Resistor, 20KΩ				
R802	1	BR12030010	Variable Resistor, 20KΩ				
S801	1	SK09080010	Keyboard Switch, (8 Key)				
PD01	1	VE 47000050					
PUUI	'	YF47230050	P.W. Board, Display				
0001	1	4723118010	Spacer, LED				
0002	i	4723053010	Cover. LED				
			3333, 325				
PM01	1	YF47850080	P.W. Soard, Feature				
	. 1						
SM01	1	SC02030102	Switch				
SM02	1	SC02020322	Switch				
PPO1	1	YF47230102	P.W. Board, Rotary Switch				
	' ∤	1177230102	F.W. Board, Hotary Switch				
SP01	1	SR24020010	Rotary Switch				
	ĺ						
	ļ						
- 1							

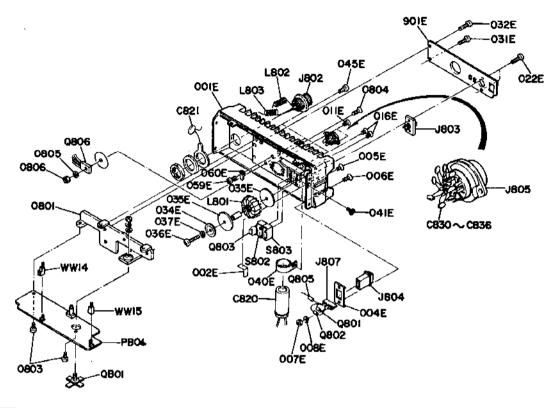
10.2 [P02-99] CHASSIS RELATED



REF.			DESCRIPTI	ON		
DESIG.	·N	PART NO.	DESCRIPTION			
	١.	4700460000	Bracket			
001Z	1	4723160020				
003Z	2	4723051510	Guide Assembly			
006Z	2	4723114010	Stopper			
008Z	2 2 2 2 2	4723154100	Knob			
011Z	2	4723118050	Spacer			
013Z	1	4723271010	Holder			
015Z	!!!	4723115010	Spring			
016Z	ין ו	4723115020	Spring			
1						
001D		4723257010	Lid, Top Cover			
001D	1	4723118090	Spacer			
003D	2	51280306U0	B.H. Tapped Screw	B3 x 6		
	1	4785853020	Label, Adjust Point	B3 X 0		
004D		4723257040	Laber, Adjust Point			
006D	;					
007D	2	4723202010	Net, Speaker			
008D	4	4723005010	Clamper B.H.M. Screw	B3 x 5		
009D	2	51100305H0		B3 X 5		
010D	1	4656259030 4723057010	Bushing			
011D	' '	4/2305/010	Leg			
012D	4	51280306U0	B.H. Tapped Screw	B3 x 6		
013D	2	4723056020	Buffer	55 7 6		
014D	6	54020301S0	Flat Washer, P.			
015D	l ĭ	4723056020	Buffer			
017D	l i l	4736120010	Insulator			
018D	l i i	4724202010	Net			
0190	2	4724055010	Collar			
020D	2	5110020850	B.H.M. Screw	B2 x 8		
021D	2	53110203B0	Hexagon Nut	~ 0		
022D	1	4220005020	Clamper			
023D	l i	53110303B0	Hexagon Nut			
901D	Ιi	4785056020	Buffer Bottom Lid			
052E	Ιi	4723109210	Shield, Upper			
053E	Ιi	4723109220	Shield, Bottom			
054E	4	51282606B0	B,H, Tapped Screw B2.6 x 6			
055E	2	51102603B0	B.H.M. Screw	B2.6 x 3		
056E	5	51532606B0	P.H. Tapped Screw			
****] - 1					
l .	1 1					

REF. Q'TY		PART NO.	DESCRIPTION				
DESIG.	N	PART NO.	DESCRIPTI				
			1				
001G	1	4723105020	Chassis, (R)				
002G	1	4723051010	Guide, (R)				
003G	4	51100304B9	B.H.M. Screw	B3 x 4			
006G	1 1	4723105030	Chassis, (L)				
007G	i	4723051020	Guide, (L)				
008G	4	51100304B9		.B3 x 4			
012G	2	51100305B9	B.H.M. Screw	B3 × 5			
017G	1	4723126010	Stay				
018G	2	51282605B0	B.H. Tapped Screw				
019G	4	51280306B0	B.H. Tapped Screw	B3 x 6			
022G	4	51100305B9	B.H.M. Screw	B3 x 5			
024G	4	51280306B0	B.H. Tapped Screw	B3 × 6			
025G	1	62030039W0	Lug	ľ			
026G	1	51102606B0	B.H.M. Screw	B2.6 x 6			
027G	1	53112603B0	Hexagon Nut				
0101	1 1	4723109130	Shield				
0102	1	4723109140	Shield	ļ			
0103	2	51102605B0	B.H.M. Screw	B2.6 x 5			
0201	1 1	4723160030	Bracket				
0202	2	51102605B0	B.H.M. Screw	B2.6 x 5			
0203	2	5110260680	B.H.M. Screw	B2.6 × 6			
E801	1	QK00801080	Speaker 1W	80			
N101	1	QK00245010	Buzzer				
Y801	1	YB00150060	Connective Cord, Sp.	eaker			
PC01	1	YF47230030	P.W. Board, Power C	ontrol			
PS01	1	YF47240090	P.W. Board, Power S	upply			
OS01	,	HT313681B0	Transistor 2SC1	368-B			
QS06	;	HT70011100	Transistor JSP60				

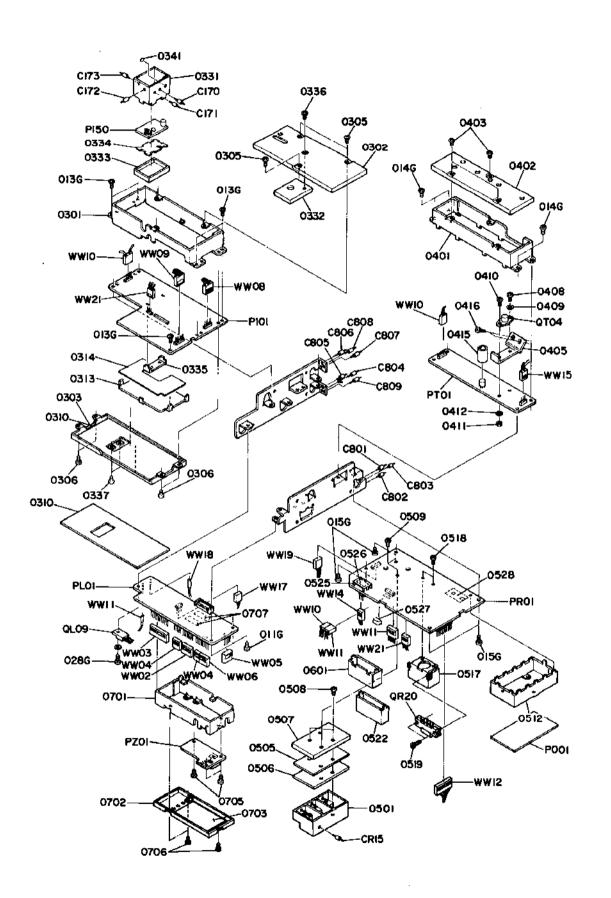
10.3 [P03-99] HEAT-SINK RELATED



	REF.	QTY	T		
	DESIG.	N	PART NO.	ION	
		†		†	
1	001E	1 !	4723267010	Heatsink	
	002E	1	4723120040	Insulator	
ł	004E	1	4723005020	Clamper	
	005E	1	51042606E0	F.H.M. Screw	F2.6 x 6
١	006E	1	51042608E0	F.H.M. Screw	F2.6 x 8
1	007E	1	53112603B0	Hexagon Nut	
ı	008E	1	54042602N0	Spring Washer	
ı	011E	2	51342606P0	F.H. Tapped Screw	F2.6 x 6
ı	016E	4	51041704E0	F.H.M. Screw	F1.7 x 4
ı	022E	2	5128260800	B.H. Tapped Screw	
ı			ļ		
ı	031E	1	51282606U0	B.H. Tapped Screw	B2.6 x 6
Į	032E] 1	51282610U0	B.H. Tapped Screw	B2.6 x 10
i	034E	1	54110149A0	Flat Washer, L.	
ı	035E	2	4618118040	Spacer	
ı	036E	1	5110031689	B.H.M. Screw	B3 x 16
ı	037E	1	54040302N0	Spring Washer	
ı	040E	1 1	4656005010	Clamper	
1	041E	1	51042606E0	F.H.M. Screw	F2.6 x 6
ı	045E	3	5110041889	B.H.M. Screw	B4 x 18
ı	059E	1	51280305B0	B.H. Tapped Screw	B3 x 5
ı	060E	1	62030039W0	Lug	
l	901E	1 1	4723265040	Indicator	
ı					
ı	0801	1	4723267020	Heatsink	
ı	0803	2	51282606B0	B.H. Tapped Screw	82.6 x 6
ı	0804	1	51042615E0	F.H.M. Screw	F2.6 x 15
۱	0805	1	54022601B0	Flat Washer, P.	
f	0806	1	53112603B0	Hexagon Nut	i
۱				• • • • • • • • • • • • • • • • • •	
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ı					ļ
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CBSIG. N	REF.	QTY	1	<u> </u>				
C821 1 DD15200300 Ceramic Cap. 20pF ±5% Ceramic Cap. 470pF ±10% C832 1 DK16471300 Ceramic Cap. 470pF ±10% C833 1 DK16471300 Ceramic Cap. 470pF ±10% C834 1 DK16471300 Ceramic Cap. 470pF ±10% C835 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% Ceramic	DESIG.	N	PART NO.	DESCRIPTION				
C821 1 DD15200300 Ceramic Cap. 20pF ±5% Ceramic Cap. 470pF ±10% C832 1 DK16471300 Ceramic Cap. 470pF ±10% C833 1 DK16471300 Ceramic Cap. 470pF ±10% C834 1 DK16471300 Ceramic Cap. 470pF ±10% C835 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% Ceramic		 ''	 -		_ _			
C821 1 DD15200300 Ceramic Cap. 20pF ±5% Ceramic Cap. 470pF ±10% C832 1 DK16471300 Ceramic Cap. 470pF ±10% C833 1 DK16471300 Ceramic Cap. 470pF ±10% C834 1 DK16471300 Ceramic Cap. 470pF ±10% C835 1 DK16471300 Ceramic Cap. 470pF ±10% C835 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% C97 CP	ŀ	1		l				
C821 1 DD15200300 Ceramic Cap. 20pF ±5% C830 1 DK16471300 C831 1 DK16471300 C832 1 DK16471300 C833 1 DK16471300 C833 1 DK16471300 C834 1 DK16471300 C835 1 DK16471300 C836 1 DK16471300 C836 1 DK16471300 C836 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% Ceramic Cap. 4	CB20	1	EG22802510	Elect Cap.	2200uE	25V		
C830 1 DK16471300 Ceramic Cap. 470pF ±10% C831 1 DK16471300 Ceramic Cap. 470pF ±10% C833 1 DK16471300 Ceramic Cap. 470pF ±10% C834 1 DK16471300 Ceramic Cap. 470pF ±10% C835 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 Ceramic Cap. 470pF ±10% Ceramic Cap. 470pF	C821	į 1	DD15200300					
C831 1 DK16471300 Ceramic Cap. 470pF ±10% C833 1 DK16471300 C834 1 DK16471300 C834 1 DK16471300 C835 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 YJ0000780 Jack, Antenna Terminal, SPK J80040010 J805 1 YJ05000040 Jack, (9P) J806 1 YP05000040 Jack, (9P) J807 1 YL01030210 Connecter, DC Jack, (9P) L803 1 LC21240010 Choke Coil Choke Coil L22310100 Cil, (10T) Coil, (10T) Coil, (10T) Coil, (10T) Coil HD20001100 Diode 10D1 Transistor SJE5576 S802 1 SS02020430 Silde Switch Silde Switch	C830	1	DK16471300					
C832 1 DK16471300 Ceramic Cap. 470pF ±10% C833 1 DK16471300 C834 1 DK16471300 C835 1 DK16471300 C836 1 DK16471300 Ceramic Cap. 470pF ±10% Ceramic Cap.	C831	1	DK16471300					
C833 1 DK16471300 Ceramic Cap. 470pF ±10% C836 1 DK16471300 C836 1 DK16471300 Ceramic Cap. 470pF ±10%	C832	1	DK16471300					
C834 1 DK16471300 Ceramic Cap. 470pf ±10% C835 1 DK16471300 Ceramic Cap. 470pf ±10% Ceramic Cap. 470pf			DK16471300			,_		
C835 1 DK16471300 Ceramic Cap. 470pF ±10% J802 1 YJ10000780 Jack, Antenna J803 1 YT02010080 Terminal, SPK J804 1 YB00040010 Jack, (9P) J806 1 YP05000040 Jack, (9P) J807 1 YL01030210 Choke Coil L802 1 LC16000010 Choke Coil L803 1 LL22310100 Cil, (10T) C801 1 HD20001100 Diode 10D1 C803 1 HD20001100 Diode 10D1 C803 1 HD20001100 Diode 10E1 C806 1 HT80053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Slide Switch	C834	1	DK16471300					
C836 1 DK16471300 Ceramic Cap. 470pF ±10% J802 1 YJ10000780 Jack, Antenna J803 1 Y702010080 J804 1 Y800040010 Connecter, DC J805 1 YJ05000040 J806 1 YP05000040 J807 1 YL01030210 L801 1 LC21240010 Choke Coil L802 1 LC16000010 Choke Coil, (5T) L803 1 LL22310100 Coil, (10T) C801 1 HD20001100 Diode 10D1 C803 1 HD20023100 Diode 10D1 C803 1 HD20023100 Diode 10D1 C806 1 HD2001100 Diode 10D1 C806 1 HD2001100 Diode 10D1 C807 1 SS02020430 Slide Switch S808 1 SS02020430 Slide Switch			DK16471300		•			
J802 1 YJ10000780 Jack, Antenna Terminal, SPK J804 1 YB00040010 Connector, DC J805 1 YJ05000040 Jack, (9P) J806 1 YP05000040 Jack, (9P) J807 1 YL01030210 Choke Coil L802 1 LC16000010 Choke Coil (5T) Call (10T) Call HD20021100 Diode 10D1 C802 1 HD2002100 Diode 10D1 C803 1 HD20023100 Diode 10D1 C803 1 HD20023100 Diode 10E1 C806 1 HD2002100 Diode 10E1 C806 1 HD2002100 Diode 10E1 C806 1 HD2002100 Diode 10E1 C806 1 HD8053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch Silde Switch	C836	1	DK16471300					
J803			Į.	,		_,,,,,		
J803	J802	1	YJ10000780	Jack, Antenna				
J805 1 YJ05000040 Jack, (9P) J806 1 YP05000040 Plug (9P) J807 1 YL01030210 Choke Coil L802 1 LC16000010 Choke Coil, (5T) L803 1 LL22310100 Coil, (10T) Q801 1 HD20001100 Diode 10D1 Q802 1 HD20001100 Diode 10D1 Q803 1 HD20023100 Diode 10E1 Q806 1 HD2002100 Diode 10E1 Q806 1 HT80053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Silde Switch			YT02010080					
J806 1 YP05000040 Plug (9P) J807 1 YL01030210 Terminal, (3P) L801 1 LC21240010 Choke Coil L803 1 LL22310100 Coil, (10T) Q801 1 HD20001100 Diode 10D1 Q802 1 HD2002100 Diode 10E1 Q803 1 HD20023100 Diode 10E1 Q806 1 HD20001100 Diode 10E1 Q806 1 HD2001100 Diode 10D1 C806 1 HT80053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Silde Switch	J804	1	YB00040010	Connecter, DC				
J807 1 YL01030210 Terminal, (3P) L801 1 LC21240010 Choke Coil L802 1 LC16000010 Choke Coil, (5T) L803 1 LL22310100 Coil, (10T) Q801 1 HD20001100 Diode 10D1 Q802 1 HD20001100 Diode 10E1 Q803 1 HD20023100 Diode 10E1 Q806 1 HD20001100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Silde Switch			YJ05000040	Jack,	(9P)			
L801	J806	1	YP05000040	Plug (9P)				
L801		1	YL01030210		(3P)			
L803 1 LL22310100 Coil, (10T) Q801 1 HD20001100 Diode 10D1 Q802 1 HD20023100 Diode 10E1 Q806 1 HD2002100 Diode 10E1 Q806 1 HT80053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Silde Switch	L801		LC21240010		,			
L803	L802		LC16000010	Choke Coil.	(5T)			
O801 1 HD20001100 Diode 10D1 O802 1 HD20001100 Diode 10D1 O803 1 HD20023100 Diode 10E1 O806 1 HD20001100 Diode 10E1 O806 1 HT80053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Silde Switch	T803	1	LL22310100					
O802 1 HD20001100 Diode 10D1 O803 1 HD20023100 Diode 10E1 O806 1 HD20001100 Diode 10E1 O806 1 HT80053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Silde Switch		i	ł	·				
O803 1 HD20023100 Diode 10E1 O806 1 HD20001100 Diode 10D1 O806 1 HT80053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Silde Switch			HD20001100	Dicde	10D1			
O806 1 HD20001100 Diode 10D1 O806 1 HT80053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Silde Switch				Diode	10D1			
O806 1 HT80053100 Transistor SJE5576 S802 1 SS02020430 Slide Switch S803 1 SS02020430 Silde Switch			HD20023100	Diode	10E1	i		
\$802 1 \$\$02020430 \$lide \$witch \$\$803 1 \$\$02020430 \$ilde \$witch			HD20001100	Diode	10D1			
S803 1 SS02020430 Silde Switch	Q806	1	HT80053100	Transistor	SJE5576			
S803 1 SS02020430 Silde Switch								
Silve Switch				Slide Switch				
PB01 1 YF47230020 P.W. Board, Booster	S803	1	\$\$02020430	Silde Switch				
PB01 1 YF47230020 P.W. Board, Booster		- 1						
	PB01	1	YF47230020	P.W. Board, Boo	Oster			
]	·				
	1					1		
QB01 1 HT321030A0 Transistor 2SC2103A	QB01	1	HT321030A0	Transistor	2SC2103A			

10.4 [M01-99] VARIOUS BOARDS AND COMMON PARTS



AEF. QTY		/	DESCRIPTION				
DESIG.	_	PART NO.	DESCRIPT	TON			
	+:-	 	+				
				1			
011G	2	51102605B0	B.H.M. Screw	82.6 x 5			
013G 014G	5 4	51102605B0 51102605B0	B.H.M. Screw R.H.M. Screw	B2.6 x 5 B2.6 x 5			
014G 015G	4	5110260580 5110260580	B.H.M. Screw B.H.M. Screw	B2.6 x 5 B2.6 x 5			
015G 028G	4	51102605B0 51102608B0	B.H.M. Screw B.H.M. Screw	B2.6 x 5 B2.6 x 8			
			B.M.M. outers	B2.b x 6			
0301	1	4723109100	Shield	J			
0302	1	4723109110	Shield	ì			
0303	1 3	4723109120	Shield	I			
0305 0306	3 4	5110020580 5110020580	B.H.M. Screw	82 x 5			
0306 0310	2	5110020580 4723120010	B.H.M. Screw Insulator	B2 × 5			
0313	1	4723120010	Insulator Shield	I			
0314	1	4785120010	Insulator	1			
0331	1	4723109090	Shield	İ			
0332	i	4723109160	Shield	Ĭ			
	1			1			
0333	1 1	4723109240	Shield	1			
0334	1 1	4723120020	Insulator	1			
0335 0336	1 1	4723109250 5110020380	Shield B H M Sorow	-			
0336 0337	1 2	51100203B0 51100203B0	B.H.M. Screw	B2 x 3			
U33 i	2	5110020380	B.H.M. Screw	B2 × 3			
0341	1	4723120080	Insulator	1			
			1020(9)(0)	j			
0401	1	4723109080	Shield	I			
0402	1 1	4723109170	Shield	I			
0403	3	51100205B0	B.H.M. Screw	B2 x 5			
0405	1	4618267050	Heatsink _				
0408		51102606B0	B.H.M. Screw	B2.6 x 6			
0409	1 1	54042602N0	Spring Washer				
0410 0411	1 1	5110261080 5311260380	B.H.M, Screw	B2.6 x 10			
0411 0412	[] [5311260380 54042602ND	Hexagon Nut Spring Washer	1			
0412 0415		54042602N0 4723267050	Spring Washer	1			
0415 0416	1 2	4723267050 51282606B0	Heatsink B.H. Tapped Screw				
U-1	-	512020000	B.H. Tapped Screw	82.6 × ti			
0501	1	4723064500	Cavity Case Assembly				
0505	1 1	4723109150	Shield	" 1			
0506	i	4723277010	Packing	I			
0507	1	4723257030	Lid, Cavity	I			
0508	2	51100206B0	B.H.M. Screw	B2 x 6			
0509 0512	2	51100208B0	B.H.M. Screw	B2 x 8			
0512 0517		4785109500 4723267030	IF Shield Assembly	I			
0517 0518	1 2	4723267030 5110260580	Heatsink R.H.M. Screw	}			
0518 0519	2	51102605B0 51102608B0	B.H.M. Screw B.H.M. Screw	82.6 x 5 82.6 x 8			
0519		4785056010	B.H.M. Screw Buffer	82.6 x 8			
0522	1	4723109030	Buffer Shield, Frontend	Ī			
0601		4723109030	Shield, Pre Amp.	Ī			
0701	1	4723109190	Shield, Control	i			
0702	1 1	4723109200	Shield, Control	1			
0703	[†	4723120030	Insulator	I			
0705	3	5110260580	B.H.M. Screw	B2.6 x 5			
0706 0707	3	5110020580 4795120020	B.H.M. Screw	B2 x 5			
0707	2	4785120020	Insulator				
J	(]	·]	1	I			
0107	1 1	3730101020	Support	1			
0108	1	3730101020	Support	I			
0120	1	51100204EU	B.H.M. Screw	B2 x 4			
0121	1	51100204E0	B.H.M. Screw	B2 x 4			
0122 0525		51100204E0	B.H.M. Screw	B2 x 4			
0525		4724109080	Shield, RX	_			
0526 0528	1	4724120010	Insulator, RX Shield	i			
0528	1	4785120030	Insulator, RX IF Coil	Case .			
1	·			1			
1	, 1			1			
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- 1	. 1	1		ļ			

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	REF.	QTY	PART NO.	DESCRIPTION
	DESIG.	N.		SECONII FICIO
				···
	C801	1	DC18202020	Feedthru Cap, 0,002μF 50V
	C802	1 1	DC18202020	Feedthru Cap. 0.002µF 50V
	C803	l í	DC18202020	Feedthru Cap, 0,002µF 50V
i	C804	l i	DC18202020	Feedthru Cap. 0.002µF 50V
	C805	l i	DC18202020	Feedthru Cap. 0.002µF 50V
	C806	1	DC18202020	Feedthru Cap. 0.002µF 50V
	C807	1	DC18202020	Feedthru Cap. 0,002µF 50V
	C808	1	DC18202020	Feedthru Cap. 0,002µF 50V
	C809	1	DC18202020	Feedthru Cap, 0,002µF 50V
				,
1	P101	1	YF47850070	P.W. Board, PLL
	P150	1	YF47850010	BW B VAA
	F130	1'	1 74 7850010	P.W. Board, V.C.O.
		1		
	C170	1	DC18202020	Feedthru Cap. 0.002μF 50V
1	C171	Ιi	DC18202020	Feedthru Cap. 0.002µF 50V Feedthru Cap. 0.002µF 50V
1	C172	l i	DC18202020	Feedthru Cap. 0.002µF 50V
ı	C173	l i	DC18202020	Feedthru Cap. 0.002µF 50V
ı		1 '	00.02020	r eed till d Cap. D.DOZZEP 509
ı	PL01	1 1	YF47850110	P.W. Board, Control
ı		1		
ļ		1	l i	
1	QL09	1	HC10029060	IC µPC14308
1		1		·
ı	PR01	1	YF47850130	P.W. Board, FIX
ı		1		
ı		١		
ı	CR15	1	DC18202020	Feedthru Cap. 0,002μF 50V
1	QR20	1	HC10031010	IC HA1366W
١	PTO1	۱.	VE43030100	But B 4 BV
ı	F101	'	YF47230120	P.W. Board, TX
ı				
ı	QT04	1 1	HT321180A0	Transistor 2SC2118
ı	_,,,,	1 '	17102710070	1101aist01 23C2116
ı	PZ01	1	YF47230042	P.W. Board, Back Up
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10.5 ELECTRICAL PARTS

REF.	'YY'ם	PART NO.	DESCRIPTION				
DESIG.	N	PAHINU.	DESCRIPTION				
P101	5	YF47850070	P.W. Board, PLL				
FIUI	'	1147030070	1.71. Dona, 1.22				
		E 1 4 0 3 0 0 F 0 0	P101-CAPACITORS				
C001 C002	1 1	EA10702530 DK18103310	Elect 100µF 25V Ceramic 0.01µF				
C003	1 1	EG33701620	Elect 330µF 16V				
C004	1	DK16102300	Ceramic 0.001µF ±10%				
C005	1	DK16471300	Ceramic 470pF ±10%				
C006	1	DK16122300	Ceramic 0.0012µF ±10%				
C020	1 1	DK16102300 DK16102300	Ceramic 0.001µF ±10% Ceramic 0.001µF ±10%				
C021 C022	¦	DK16102300	Ceramic 0.001µF ±10%				
C022	li	DK16102300	Ceramic 0.001µF ±10%				
C024	1	DK16102300	Ceramic 0.001µF ±10%				
C025	1	DK16102300 DK16102300	Ceramic 0.001μF ±10% Ceramic 0.001μF ±10%				
C026 C027	1 1	DK16102300	Ceramic 0.001µF ±10%				
C028	i	DK16102300	Ceramic 0.901µF ±10%				
C029	i	DK16102300	Ceramic 0.001µF ±10%				
C030	1	DK16102300	Ceramic 0.001µF ±10%				
C031	1	DK16102300	Ceramic 0.001µF ±10%				
C032	1	DK16102300 DD15300300	Ceramic 0.001µF ±10% Ceramic 30pF ±5%				
C100	1	0010300300	OBIGINIC SUPE 1976				
C101	1	DD15510300	Ceramic 51pF ±5%				
C102	1	DD15150300	Ceramic 15pF ±5%				
C103	1	CT12000090	Trimming 20pF				
C104	1	EV10601060	Elect 10µF 10V				
C105	1	EV10403560 EV47501060	Elect 0.1μF 35V Elect 4.7μF 10V				
C106 C107	;	DK16102300	Ceramic 0.001μF ±10%				
C108	i	DS17104010	Semicon 0.1µF ±20%				
C109	i	EA10701030	Elect 100µF 10V				
C110	1	DS17683010	Semicon 0.068µF ±20%				
C111	۱,	EA10701030	Elect 100µF 10V				
C120	i	DK16102300	Ceramic 0.001µF ±10%				
C121	1	DD15300330	Ceramic 30pF ±5%				
C122	1	DD10010300	Ceramic 1pF ±0.25pF				
C123	1 1	DK16102300 DK16122300	Ceramic				
C124 C125	¦	DK16102300	Ceramic 0.00124F ±10%				
C130	i	DD15300300	Ceramic 30pF ±5%				
C131	1	DK16122300	Ceramic 0.0012µF ±10%				
C132	1	DK16122300	Ceramic 0.0012µF ±10%				
C133	١.	EV22502560	Elect 2.2μF 25V				
C133	1 1	DK16102300	Elect 2.2μ+ 25V Ceramic 0.001μF ±10%				
C140	i	DD15300300	Ceramic 30pF ±5%				
C141	1	DK16122300	Ceramic 0.0012µF ±10%				
C142	1	DK16122300	Ceramic 0.0012μF ±10%				
C143	1	DK16122300	Ceramic 0.0012µF ±10%				
C144	1	DK16102300 DK18102300	Ceramic 0.001µF ±10% Ceramic 0.001µF 50V				
C145 C200	1 1	DD10030300	Ceramic				
C201	t	DK16102300	Ceramic 0.001µF ±10%				
C202	1	DD10040300	Ceramic 4pF ±0.25pF				
C203	1	DK16471300	Ceremic 470pF ±10%				
C204	1	DK16122300	Ceramic 0.0012µF ±10%				
C205	1 1	DD15101350 DK16102300	Ceramic 100pF ±5%				
C206 C207	1 1	EA47601030	Ceramic 0.001μF ±10% Elect 47μF 10V				
C208	1 2	DK18103310	Ceramic 0.01µF				
C209	1	DK16102300	Ceramic 0.001µF ±10%				
C210	1	DK16122300	Ceramic 0.0012µF ±10%				
C211	t	DK16102300	Ceramic 0.001µF ±10%				
C212	1 1	DK16102300	Ceramic 0.001µF ±10%				
C213	1	DD15470300	Ceramic 470pF				
L		<u></u>	<u></u>				

REF.	Q'TY	DART NO	D. CORUNTION
DESIG.	N	PART NO.	DESCRIPTION
1			
C301	!	CT12000090	Trimming 20pF
C302	1 !	DD10020350	Ceremic 2pF ±0.25pF
C303 C304	1 .	DK16122300 CT12000090	Ceramic 0.0012µF ±10% Trimming 20pF
C304	1	DD10020350	Ceramic 2pF ±0.25pF
C306	1 1	DK16122300	Ceramic 0,00124F ±10%
0300	Ι'.	DK19122000	Caldinic Visoria = 10%
C309	1	DK16102300	Ceramic 0.001µF ±10%
C310	1	CT12000090	Trimming 20pF
C311	1	DD10020350	Ceramic 2pF ±0.25pF
C312	וו	DK16102300	Ceramic 0.001µF ±10%
C313	1	DK16102300	Ceramic 0.001µF ±10%
C314	1	DK16102300	Ceramic 0.001µF ±10%
C315	1	DK16122300	Ceramic 0.0012µF ±10%
C316	۱ ،	DD15101050	Ceramic 100pF ±5%
C317	;	DD15620010	Ceramic 62oF ±5%
C318	l i	DK18103310	Ceramic 0.01µF
C319	i	DK18103310	Ceramic 0.01µF
C320	1	DK16102300	Ceramic 0.001µF ±10%
C321	1	DD10010300	Ceramic 1pF ±0.25pF
C401	1	EV33403560	Elect 0.33μF 35V
C402	1	EV47600660	Elect 47μF 6.3V
C404	1	EA22701030	Elect 220µF 10V
C405	1	EV10502560	Elect 1µF 25V
C406	١.	EV22601060	Elect 22µF 10V
C406	1	DS17222010	Semiçon 0.0022µF ±20%
C408	;	DK18103310	Ceramic 0.01µF
C409	l i	EV10502560	Elect 1µF 25V
C410	;	EV10403560	Elect 0.1µF 35V
C412	ĺi	EA10601690	Elect 10µF 16V
C413	1	EA10601690	Elect 10µF 16V
C414	1	EV10502560	Elect 1µF 25V
C415	1	DF16683300	Film 0.068µF ±10%
C417	1	DF16683300	Film 0,068µF ±10%
l	l _		
C418	1	DF16103300	Film 0.01µF ±10% Elect 10µF 10V
C419	1 1	EV10601060 DK16102300	Elect 10µF 10V Ceramic 0.001µF ±10%
C420	'	DK16102300	Cerainic 0.001µF 110%
			and Resistance
			P101-RESISTORS (All Resistors are ±5% and %W)
R001	1	GJ05680010	68Ω 1W
R002	;	GD05101140	100Ω
R003	∣i	GD05101140	100Ω
R004	i	GD05272140	2,7ΚΩ
R005	1	GD05222140	2.2ΚΩ
R006	1	GD05272140	2.7ΚΩ
R007	1	GD05271140	270Ω
R008	1	GD05682140	6.8KΩ
R009	!	GD05333140	33KU
R010	1	GD05101140	100Ω
R011	١,	RC00000120	0Ω
R020] i	GD05682140	6.8KΩ
R021	1 i	GD05682140	6.8KΩ
R022	1	GD05682140	6.8KΩ
R023	1	GD05682140	6.8KΩ
R024	1	GD05682140	6. 8KΩ
R025	1	GD05682140	6.8KΩ
R026	1	GD05682140	6.8KΩ
R027	1	GD05682140	6.8KΩ
R028	Ι'	GD05682140	6.8KΩ
	1	l	<u> </u>

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ł	REF. DESIG.	QTY	PART NO.	DESCRIPTION		- 1	REF. DESIG.	N N	PART NO.	DESCRIPTION	
ŀ	UÇSIG.	N	·			ı	Degita.	N	_	<u></u>	
ı						- 1					
1	R029	1	GD05682140	6.8K Ω		- 1	R411	1 1	GD05272140	2.7KΩ	
1	R030	1	GD05682140	6.8KΩ		- 1	R412	1	GD05272140	2.7KΩ	
1	R031	1	GD05682140	6.8KΩ		- 1	R413	1	GD05332140	3.3KΩ	
1	R032	1 1	GD05682140	6.8K Ω		- 1	R414	1	GD05561140	560Ω	
1	R120	1	GD05103140	10KΩ	i	- 1	R415	1 1	GD05562140	5. 6 ΚΩ	
1	R121	1	GD05103140	10ΚΩ	1	- 1	R416	1	RA01030070	10KΩ	Trimming
1	R122	1	GD05561140	560Ω		·	R417	1	GD05272140	2.7KΩ	
1	R123	1	GD05101140	100Ω	į	- 1	R418	1	RC00000120	$\Omega \Omega$	
1	R124	1 1	GD05103140	10KΩ			R419 R420	1 1	GD05333140 GD05472140	33KΩ 4.7KΩ	
1	R125	1	GD05153140	15ΚΩ			N420	'	GD05472140	4.7636	
ŀ	R126	1	GD05471140	470Ω							
ı	R127	l i l	GD05101140	100Ω							
ı	R128	1	GD05101140	100Ω							
ı	R130	1	GD05102140	1ΚΩ				1			
ı	R131	1	GD05472140	4.7KΩ	·			i I			
ı	R132	1 1	GD05331140	330Ω	1			1			
1	R133	1	GD05101140	100Ω			0004	,		P101-SEMICO	
	R134	1	GD05472140	4.7KΩ			0001	1 1	HC10022060 HD30017090	IC Zener	μΡC78L08 BZ-090
	R135	1	GD05102140	1KΩ	Trimming		Q004 Q101	1 1	HD30017090 HC10046050	∠ener IC	BZ-090 TC5081P
1	R136	1	RA04720050	4.7ΚΩ	Trimming		Q101	;	HC10048050	ic	TC5082PL
Į	R137	١,	RC00000120	Ω0			Q102	1	HC10023050	IC	TC9122P
1	R140	;	GD05102140	1ΚΩ			0104	;	HT107331R0	Transistor	2SA733(R)
-	R141	Ιi	GD05472140	4.7KΩ		1	Q120	l i	HT304611B0	Transistor	2SC461(B)
-	R142	Ιi	GD05331140	330Ω		1	Q121	1	HT304611B0	Transistor	2SC461(B)
-	R143	l i	GD05101140	100Ω			Q122	1	HT304611B0	Transistor	2SC461(B)
-	R144	1	GD05561140	560Ω			Q123	1	HT304611B0	Transistor	2SC461(B)
-	R145	1	GD05333140	33KΩ						•	
-	R200	1	GD05224140	220KΩ			Q124	1	HT312131B0	Transistor	2SC1213(B)
-	FI 201	1	GD05101140	100Ω			Q125	1	HT309451Q0	Transistor	2SC945(Q)
-	R202	1	GD05561140	560Ω			Q126	1	HT309451Q0	Transistor	2SC945(Q) 2SC461(B)
-	0000	١.	CDOFFE	1508.0			Q201 Q202	1	HT304611B0 HT304611B0	Transistor Transistor	2SC461(B)
-	R 203 R 204	1 1	GD05154140	150ΚΩ 1 00 Ω			0202	i	HC10017210	IC	BA401
-	R205	l ¦	GD05101140 GD05472140	4.7KΩ			0204	l i	HT304601B0	Transistor	2SC460(B)
-	R206	Ιi	GD05272140	2.7ΚΩ			Q301	i	HD20011050	Diode	1\$1555
-	R207	Ιi	GD05102140	1ΚΩ			0302	1	HD20011050	Diode	1\$1555
-	R208	1	GD05101140	100Ω	i						
ļ	R209	1	GD05154140	150KΩ	•		Q304	1	HD20011050	Diode	1\$1555
ł	H210	1	GD05561140	560Ω			Q305	1	HT304601B0	Transistor	2SC460(B)
ŀ	A211	1	GD05101140	100Ω			Q306 Q307	1	HD20011050	Diode	181555
١	R301	1	GD05272140	2.7ΚΩ		i		1	HD20011050	Diode	1\$1555
ı	R302	1	GD05272140	2.7ΚΩ	i		Q308 Q401	1 1	HD20011050 HC10001390	Diode IC	181555 SL-1626C
1	R304 R310	1 1	GD05272140 GD05272180	2.7KΩ 2,7KΩ 1/8W			0402	'	HT309001F0	Transistor	2SC900(F)
ĺ	R311		GD05272180	2.7KΩ 1/8W			0403	Ιi	HD20011050	Diode	1S1555
ı	R315	1	GD05182140	1.8KΩ			0404	Ιi	HD20011050	Diode	181555
اد	R316	Ιi	GD05152140	1.5KΩ				1			
	R317	1	GD05471140	470Ω					[.		
1	R319	1	GD05101140	100Ω				!			
1	R320	1	GD05101140	100Ω							
1	R402	1	GD05105140	1MΩ				١.	VD00004540	P101-MISCEL	
1	R403	1	GD05680140	68 Ω	-		J101	1	YP06001540	Plug, Progra	
1	R404	1 1	RA02220100	2.2KΩ	Trimming		J125 J301	1	YP08001200 YJ03000050		Dutput Socket
1	R405 R406	1 1	GD05223140 GD05153140	22ΚΩ 15ΚΩ			J320	∣i	YP06001200	Plug, X'tal	
-	R410	Ιi	GD05222140	2.2KΩ			J401	i	YP06000880	Plug, Power	
1	11410	1 '	0000222110	2.2			J431	i	YP06001480		02A (CTN-5)
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REF.	Q'TY	PART NO.	DESCRIPTION
DESIG.	N	PART NO.	DESCRIPTION
L120	1 1	LA70280010	Ant, Coil, TX PLL Out
L121	1	LA70280050	Ant. Coil, RX PLL Out
L122	1 1	LA70280050	Ant, Coil, VCO
L201	1	LC11530020	Choke Coil, 15µH
L202	!	LC12720020	Choke Coil, 2.7µH
L301	1	LC11020020	Choke Coil, 1µH
L302	1	LC11020020	Choke Coi∤, 1⊭H Choke Coil, 1⊭H
L304	1 1	LC11020020 LC13940010	Choke Coil, 1µH Choke Coil, 390µH
L305	;	LC11020020	Choke Coil, 1µH
L306 L307	li	LA70280050	Ant. Coil, PLL Local OSC
L308	i	LO70280010	OSC Coil, PLL Local OSC
L401	i	LC24760010	Choke Coil, 47mH
L-101	'	2024700070	Grove con,
X101	1	XY40512002	Cristal 5.12MHz
X301	l i	XB301010G2	Cristal 46.000MHz, TX
X302	i	XB301011G2	Cristal 42.433MHz, RX
	1		, '
P150	1	YF47850010	P150-VCO CIRCUIT BOARD P.W. Board, VCO
	1		P150-CAPACITORS
C150	1	DK16102300	Ceramic 0.001µF ±10%
C151	3	DK16102300	Ceramic 0.001µF ±10%
C152	1	EA10602530	Elect 10µF 25V
C153	1	DD10030300	Ceramic 3pF ±0.25pF
Ç154	1	DD11100300	Ceramic 10pF ±0.5pF
C155	1	DD11100300	Ceramic 10pF ±0.5pF
C156	1	DD15240300	Ceramic 24pF ±5%
C157	1	DD10010300	Ceramic 1pF ±0.25pF
C158	1	DD15390300	Ceramic 39pF ±5%
C159	1	DS17392010	Semicon 3900pF ±20%
	1.		
C160	1	EV33601060	Elect 33µF 10V
C170	1	DC18202020	Feedthru 2000pF
C171	1 1	DC18202020	Feedthru 2000pF
C172	1	DC18202020	Feedthru 2000pF
C173	1	DC18202020	Feedthru 2000pF
R150 R151 R152 R153 R154 R155 R156	1 1 1 1 1 1 1	GD05101140 GD05101140 GD05101140 GD05222140 GD05222140 GD05473140 GD05103140 GD05104140	P150-RESISTORS (All Resistors are ±5% and %W) 100Ω 100Ω 100Ω 2.2KΩ 47KΩ 10KΩ 100ΚΩ
0151	.	NO ADDOTORO	P150-SEMICONDUCTORS Varicap 1SV50
Q151	1 1	HD40001060	1
Q152 Q153	1	HD40001060	Varicap 1SV50 Varicap 1SV50
Q154	;	HF200191B0	F.E.T. 2SK19TM(GR)
G 134	'	20013180	L.E.T. ZORTOTHIOTI
			P150-COILS
L150	1	LA12036060	Ant. Coil, VCO
L151	1	LC12720020	Choke Coil, 2.7µH
L152	1	LC11020020	Choke Coil, 1µH
L153	1	LC11020020	Choke Coil, 1µH
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REF. DESIG.	Q'TY N	PART NO.	DESCRIPTION
	<u>"</u>		
			PB01-BOOSTER
] .	_		CIRCUIT BOARD
PB01	1	YF47230020	P.W. Board, Booster
]		!	
CB01	1	CT11050010	PB01-CAPACITORS Trimming 12pF
CB02	1	ĐD15510300	Ceramic 51pF ±5%
CB03 CB04	1 1	DD15150300 EG47503520	Ceramic 15ρF ±5% Elect 4,7μF 35V
CB05	1	CT11500010	Trimming 15pF
CB06 CB07	1 1	DD15180300 DD15200300	Ceramic 15pF ±5% Ceramic 20pF ±5%
CB08	1	DD15150300	Ceramic 15pF ±5%
CB09	1 1	DD15150300 DD10005010	Ceramic 15pF ±5% Ceramic 0.5pF ±0.25pF
""			
CB11 CB12	1	DK16122300 DK16102300	Ceramic 0.0012µF ±10% Ceramic 0.001µF ±10%
CB13	i	DD15300300	Ceramic 30pF ±5%
CB14 CB15	1 1	DK18103310 DK16471300	Ceramic 0.01µF +100% -0 Ceramic 470pF ±10%
CB16	1	DD15200300	Ceramic 20pF ±5%
CB17 CB18	1 1	DK16471300 DK16471300	Ceramic
CB19	i	DD10030300	Ceramic 3pF ±0.25pF
CB20 CB21	1:	DD15300300 DD15200300	Ceramic 30pF ±5% Ceramic 20pF ±5%
CB22	;	CT11050010	Trimming 12pF
CB24	1 !	DD15200300 EV33502560	Ceramic 20pF ±5% Elect 3.3µF 25V
CB25	1	DC18202020	Feedthru 2000pF
CB31	1 !	DC18202020	Feedthru 2000pF
CB32	1 1	DC18202020 DC18202020	Feedthru 2000pF Feedthru 2000pF
CB34	1	DC18202020	Feedthru 2000pF
			PB01-RESISTORS
R801	1	GD05020140	2Ω ±5% ¼W 1 330Ω ±5% ¼W
R802 R803	1	GD05331140 GD05101140	330Ω ±5% ¼W 100Ω ±5% ¼W
RB05	1	RA01040120	100KΩ Trimming
RB06 RB07	1 1	GD05331140 RA01020150	330Ω ±5% ¼W 1KΩ Trimming
RB08	1	GF05101120	100Ω ±5% ½W
R809	1	RC00000140 RC00000140	0Ω
RB11	1	RC00000140	0Ω
RB12	1 1	RC00000140 RC00000140	00 00
""	1 .		PB01-SEMICONDUCTORS
QB01 QB02	1 1	HT321030A0 HD20011050	
Q803	i	HD10001050	Diode 1N60
QB04	1 1	HD20003200 HD20001200	
QB05	ì	HD20011050	Diods 181555
QB07	1 1	HD20011050 HD10001050	
QB08 QB09		HD10001050	Diode 1N60
QB10	1	HD30033090	Zener WZ-052
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REF.	YTD		
DESIG.	N N	PART NO.	DESCRIPTION
			•
			PB01-MISCELLANEOUS
JB01	1	YP06001480	Plug (2P)
JB02	1	YP06001480	Plug (2P)
LB01	1	LM42830010	Twist Coil
LB02	i	LC12010012	Choke Coil (8T) 0.2µH
LB03	l i l	LC16000010	Choke Coil (5T)
LB04	i	LC12500020	Choke Coil (1T)
LB05	1	LK30802040	Coil (4T)
L806	1	LC16000010	Choke Coil (5T)
LB07	1	LL26301050	Coil (8T)
LB08	1	LC11510012 LF50080030	Choke Coil (3T)
LB09 LB10	1 1	LC16000010	Ant. Coil Choke Coil (5T)
LDIO	' '	201000010	Choke Coli (S1)
			PC01-POWER CONTROL
			CIRCUIT BOARD
PC01	1	YF47230030	P.W. Board, Power Control
1			
			PC01-CAPACITORS
CC01	1	DK16102300	Ceremic 0.001µF ±10%
CC02	1	DK16102300	Ceramic 0.001µF ±10%
CC03	1	DK16102300	Ceramic 0.001μF ±10%
CC04	1	DK16102300	Ceramic 0.001μF ±10%
CC05	1	DK16102300	Ceramic 0.001µF ±10%
CC06	1	EG47503520	Elect 4.7µF 35V
CC07	1 1	DK18103310 DK18103310	Ceramic 0.01µF +100% -0 Ceramic 0.01µF +100% -0
CC09 CC10	'i	DK18103310	Ceramic 0.01μF +100% -0 Ceramic 0.01μF +100% -0
CC11	l i l	DK18103310	Ceramic 0.01µF +100% -0
	'		0.00.7.
			PC01-RESISTORS
			(All Resistors are ±5% and %W)
RC01	1	GJ05121020	120Ω 2W
RC02	1	GD05151140	i
RC03	1	GD05222140	2.2ΚΩ
RC04	1 1	GD05334140	330KΩ
RC05	1 1	GD05473140 GD05222140	47KΩ
RC06 RC07		RA02220100	2.2KΩ 2,2KΩ Trimming
RCOB	i	RA05030110	47KΩ Trimming
RC09	i	GD05471140	470Ω
RC10	1	GD05104140	100KΩ
B.5.		O DAFFARET	100
RC11	1	GD05100140 RA05030110	10Ω 47KO Trimming
RC12 RC13		GD05682140	47KΩ Trimming 6.8KΩ
RC15	;	GD05082140	100Ω
-		_	
QC01	.	LITAGAZATIO	PC01-SEMICONDUCTORS Transistor 2SD471
QC02	1 1	HT404711L0 HT304601B0	Transistor 2SD471 Transistor 2SC460(B)
0003	;	HT304601B0	Transistor 25C460(B)
QC04	1	HT304601B0	Transistor 2SC460(B)
QC05	1	HD20001210	Diode 1\$2473
QC06	1	HD20001210	Diode 1S2473
QC07	1	HD30017090	Zener BZ-090
	·		

REF. DESIG.	QTY	PART NO.	DESCRIPTION
	14		PD01-DISPLAY CIRCUIT BOARD
PD01	1	YF47230050	P.W. Board, Display
CD01	1	DK16471300	PD01-CAPACITOR Ceramic 470pF ±10%
RD02 RD03	1	GD05682180 GD05123180	PD01-RESISTORS 6.8KΩ ±5% 1/8W 12KΩ ±5% 1/8W
QD01 QD02 QD03 QD04 QD05 QD06 QD07 QD08 QD10 QD11 QD11 QD13 QD14 QD15 QD16 QD17 QD17 QD18	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	H110006030 H110006030 H110006030 H110006030 H110002340 H110002340 H110002340 H110002340 H110002340 H110002340 H110002340 H110002340 H110003340 H110003340 H110003340 H110003340 H1100031210	PD01-SEMICONDUCTORS L.E.D. 75EG, Green L.E.D. 75EG, Green L.E.D. 75EG, Green L.E.D. 75EG, Green L.E.D. 75EG, Green L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4150, Yellow L.E.D. HP-5082-4100, Read
QD19 QD20 QD21	1 1 1	HD20001210 HC10001380 HV00002060	Diode 1\$2473 IC UAA-180 Veristor VD1212
PL01	1	YF47850110	PL01-CONTROL CIRCUIT BOARD P.W. Board, Control
CL01 CL02 CL03 CL04 CL05 CL06 CL07 CL08 CL09 CL10 CL11 CL12	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	DO15330300 EV22501660 DK16102300 EA22701630 EA33701030 EG10801620 DK16471300 DK16471300 EV10503560 DK16471300 DK16471300	CL01-CAPACITORS Ceramic 33pF ±5% Elect 2.2μF 16V Ceramic 0.001μF ±10% Elect 220μF 16V Elect 330μF 10V Elect 1000μF 16V Ceramic 470pF ±10% Ceramic 470pF ±10% Elect 1000μF 16V Elect 1μF 35V Ceramic 470pF ±10% Ceramic 470pF ±10% Ceramic 470pF ±10%
RL03 RL04 RL05 RL06 RL07 RL08 RL09 RL10 RL11 RL11	1 1 1 1 1 1 1 1 1	GD05473140 GU05330120 GU05330120 GU05330120 GU05330120 GU05330120 GU05330120 GU05330120 GU05320120 GD05562140	PL01-RESISTOR\$ (All Resistors are ±5% and %W) 47ΚΩ 33Ω

REF.	QTY	PART NO.	DESCRIPTION
DESIG.	N	PARTNO.	DESCRIPTION
	:		
RL13	1	GD05223140	22 ΚΩ
RL14	1	GD05333140	33K 11
RL15	1	GD05185140	1,8ΜΩ
RL16	1	GD05333140	33KΩ
RL17	1	RA04730100	47KΩ Trimming
RL18	1	GD05333140	33КΩ
RL20	1	G005471140	470Ω
RL22	1	GD05562140	5.6KΩ
RL23	1	G005333140	33ΚΩ
RL24	1	GD05333140	33KΩ
GL01	1	BW10333010	33KΩx 4 10% R-Block
GL02	1	BW10333010	33KΩx 4 10% R-Block
GL03	1	BW10333010	33KΩx 4 10% R-Block
GL04	1	BW10333010	33KΩx 4 10% R-Block
1	-		PL01-SEMICONDUCTORS
QL01	1	HC10003370	IC MP1107
QL02	i	HC10005370	IC TMS1024
QL03	l i l	HC10016060	IC #PA57C
QL04	l i	HC10011210	IC TA76
QL05	lil	HC10011210	IC TA76
QL06	1	HC10012170	IC MC14016
QL07	l i l	HC10012170	IC MC14016
QL08	l i	HD20401210	Diode DAP401
GL09	Ιί	HC10029060	IC µPC14308
QL10	Ιi	HC20011050	Diode 1S1555
1 2510	l '	11020011030	Diode FOI 550
QL11	۱ ،	HC20011050	Diode 181555
		HC20011050	Diode 1\$1555
QL12	1 1	HC20011050	Diode 1\$1555
QL13			
QL14	1	HC20011050	
QL15	1	HC20011050	Diode 1\$1555
QL16	1	HC20011050	Diode 1\$1555
QL17	1	HC20011050	Diode 151555
QL18	1	HT31213180	Transistor 2SC1213B
QL19	1	HD30060090	Zener XZ094
QL20	1	HD20011050	Diode 1S1555
QL21	1	HD20001100	Diode 10D-2
QL22	1	HD20011050	Diode 1S1555
	-		
1	İ		PL01-MISCELLANEOUS
JL01	1	YJ06002100	Jack (13P)
JL02	1	YP06001160	Plug (12P)
JL03	1	YP06001800	Ptug (7P)
JL04	1	YP06001200	Plug (5P)
JL05	1	YP06001280	Plug (11P)
JL06	1	YP06000890	Plug (3P)
J1_07	1	YP10002210	Piug (1P)
JL08	1 1	YP10002210	Plug (1P)
JL09	1	YP06001820	Plug (4P)
ì	1		
LL01	1	LC13940010	Choke Coil, 390µH
LL02	1	LC26550010	Chake Cail, 6.4mH
	1		
	1	1	
	,	1	PMG1-FEATURE CONTROL
1	i	1	CIRCUIT BOARD
PM01	1 1	YF47850080	P.W. Board, Feature Control
1	l `	1	
1	1	ļ	
1	1	1	PM01-CAPACITORS
CM01	l 1	DK18103310	Ceramic 0.01µF
CM02	i	DS17153010	Semicon 0.015µF ±20%
CM03	1	EV10403560	Elect 0.1µF 35V
CM04	l i	EV10403560	Elect 0.1µF 35V
CM05	;	OD15101370	Ceramic 100pF ±5%
CONTO	Ι'	30,0,0,0,370	Solutio (Sept 1070
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1	1	1	
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REF.	QTY	PART NO.	DE	SCRIPTION
DESIG.	N			
CM06	1	DD15101370	Ceramic	100pF ±5%
CM07	1 1	EV33502560	Elect	3.3µF 25∨
CM08	1 1	EV33502560	Elect	3.3µF 25V
CM09	1	EV22601660	Elect Ceramic	22µF 16V 0.01µF
CM10 CM15	1 1	DK18103310 EV10502560	Elect	1μF 25V
CWIS	i '	2 10302380	Liuox	1,000
			PM01-RES	
			(All Resisto 	ors are ±5% and 1/8W)
RM02	1	GD05102180	1ΚΩ	
RM03	1	GD05103180	10KΩ	
RM04	!	GD05103180	10KΩ	
RM05	1 1	GD05103180 GD05473180	10KΩ 47KΩ	
RM07	Ιi	GD05473180	47KΩ	
RM08	Ιi	GD05473180	47KΩ	
RM09	i	GD05473180	47KΩ	
	İ			(
RM11	1	GD05223180	22KΩ	
RM12	1	GD05103180	10KΩ	
RM13	1	G005822180	8.2KΩ	
RM14 RM15	1 1	GD05103180 GD06473180	10KΩ 47KΩ	
RM16	;	GD05473180	33KΩ	
RM17	l i	GD05333180	33KΩ	
RM18	1	GD05102180	1KΩ	
RM19	i	GD05102180	1KΩ	
RM20	1	GD05392180	3.9KΩ	
RM21	1	GD05392180	3.9KΩ	
RM22	1	GD05682180	6.8KΩ	
FIM23	1	GD05682180	6.8KΩ	
RM24	1	GD05392180	3.9KΩ	
RM25 RM26	1 1	GD05392180 GD05562180	3.9KΩ 5.6KΩ	
RM27	1 1	GD05562180	5.6KΩ	
RM28	Ιi	GD05222180	2.2ΚΩ	
RM29	i	GD05682140	6.8KΩ	%W
RM30	1	GD05222180	2.2KΩ	
			PM01-SEM	ICONDUCTORS
QM02	1	HC10014170	lic	MC14011BP
QM03	1	HC10021050	IC	TC7400
QM04	1	HC10021050	IC	TC7400
QM05	1	HC10014170	l ic	MC140118P
QM06	1	HC10022060 HT320211R2	IC Transistor	μPC7&1:08 (2SC2021
QM07	1 1	HT320211R2	Transistor	0000004
OM08	1	HT320211R2	Transistor	28C2021 28C2021
QM10	i	HT320211R2	Trensistor	2SC2021
QM11	1	HT320211R2	Transistor	28C2021
QM12	1	HT320211R2	Transistor	2SC2021
QM13	1	HT320211R2	Transistor	2SC2021
QM18	1	HD20011050	Diode	1\$1555
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REF.	QTY	PART NO.	DESCRIPTION
DESIG.	N	12(1) (10)	Deddill 1101
			PROTEST AND DE
13401	١,	V000001770	PM01-MISCELLANEOUS Plug (12P) 3022-12B
			Plug (12F) 3022-12B Plug (11P) 3022-11B
			Plug 3022-0-98
			Plug (2P) 3022-2B
	ı ·		Plug (9P) 3022-98
JINIOS	Ι'	71 00007750	Fing (31) 5022-56
SM01	1 1	SC02030102	Switch, 3 Position
SM02	1	SC02020322	Switch, 2 Position
	l		•
	l		
	l		PP01-ROTARY SWITCH
	l		CIRCUIT BOARD
PP01	1	YF47230102	P.W. Board, Rotary Switch
	Ι.		
DPA	١. ١	0000001111	Barbara 9300 15% (5
			Resistor 270Ω ±5% ½W
			Resistor 1KΩ ±5% ¼W Resistor 1KΩ ±5% ¼W
nru3	' '	GUUD 102140	energetor (1/24 TD2) WAA
QP01	1	HW10001060	Photo Unit PS4001
			Photo Unit PS4001
4102	'	111110001000	Fricto Cint
SP01	1	SR24020010	Rotary Switch, 24 Position
			PR01-RX CIRCUIT BOARD
PRO1	1	YF47850130	P.W. Board, RX
	_	.	PRO1-CAPACITORS
			Ceramic 470pF ±10%
			Ceramic 0,001µF ±10%
			Ceramic 0.001µF ±10% Ceramic 0.001µF ±10%
	-		Ceramic $0.001\mu F \pm 10\%$ Ceramic $20\rho F \pm 5\%$
			Ceramic 30pF ±5%
-			Ceramic 0,001µF ±10%
	ì		Ceramic 0.001µF ±10%
CQ09	1	DK16102300	Ceramic 0.001µF ±10%
		i	·
CR04	1	DK16102300	Ceramic 0.001 µF ±10%
CR07	1	DD10005010	Ceramic 0,5pF 50V
CR08	1	DD10050330	Ceramic 5pF
CR09	1	DK16102300	Ceramic 0.001µF ±10%
CR 10		DD11070330	Ceramic 7pF ±0.5pF
			Ceramic 24pF ±5%
_			Ceramic 0.001µF ±10%
			Ceramic 0.001µF ±10%
UR 14	'	DK 16102300	Ceramic 0.001µF ±10%
CR15	,	DC18202020	Feedthru 2000pF
			Trimming 6pF
			Trimming 6pF
	_	CITOBOUGGE	
CR17 CR18	1	CT10600030 CT10600030	
CR17	1		
CR17 CR18 CR19 CR20	1 1 1	CT10600030	Trimming 6pF
CR17 CR18 CR19 CR20 CR21	1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001µF ±10% Ceramic 0.001µF ±10%
CR17 CR18 CR19 CR20 CR21 CR22	1 1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001 \(\mu \) ±10% Ceramic 0.001 \(\mu \) ± 10% Ceramic 0.01 \(\mu \) = ±10%
CR17 CR18 CR19 CR20 CR21 CR22 CR23	1111	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010 EV10403560	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001µF ±10% Ceramic 0.01µF Elect 0.1µF 35V
CR17 CR18 CR19 CR20 CR21 CR22	1 1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001 \(\mu \) ±10% Ceramic 0.001 \(\mu \) ± 10% Ceramic 0.01 \(\mu \) = ±10%
CR17 CR18 CR19 CR20 CR21 CR22 CR23 CR24	1 1 1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010 EV10403560 DS17103010	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001μF ±10% Ceramic 0.001μF ±10% Ceramic 0.01μF 35V Semicon 0.01μF 35V Semicon 0.01μF 35V Ceramic 0.01μF 35V Ceramic 0.01μF 35V Ceramic 0.01μF 35V Ceramic 0.01μF
CR17 CR18 CR19 CR20 CR21 CR22 CR23 CR24	1 1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010 EV10403560 DS17103010 DS17103010	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001μF ±10% Ceramic 0.001μF = 10% Ceramic 0.01μF Elect 0.1μF 35V Semicon 0.01μF
CR17 CR18 CR19 CR20 CR21 CR22 CR23 CR24 CR25 CR26	1 1 1 1 1 1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010 EV10403560 DS17103010 DS17103010	Trimming 6pF Ceramic 5pF ±0.25pF
CR17 CR18 CR19 CR20 CR21 CR22 CR23 CR24 CR25 CR26 CR27	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010 EV10403560 DS17103010 DS17103010 DS17103010 DD15160330	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001μF ±10% Ceramic 0.01μF 35V Semicon 0.01μF Semicon 0.01μF Semicon 0.01μF Semicon 0.01μF Ceramic 15pF ±5% Semicon 0.01μF Ceramic 15pF ±5% Semicon 0.01μF Ceramic 15pF ±5% Semicon 0.01μF Ceramic 15pF ±5% Semicon 0.01μF Ceramic 15pF ±5% Semicon 0.01μF Ceramic 15pF ±5% Semicon 0.01μF Ceramic 15pF ±5% Semicon 0.01μF Ceramic 0.01μF
CR17 CR18 CR19 CR20 CR21 CR22 CR23 CR24 CR25 CR26	1 1 1 1 1 1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010 EV10403560 DS17103010 DS17103010	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001μF ±10% Ceramic 0.01μF Elect 0.1μF 35V Semicon 0.01μF Semicon 0.01μF Semicon 0.01μF Ceramic 15pF ±5% Ceramic 24pF ±5%
CR17 CR18 CR19 CR20 CR21 CR22 CR23 CR24 CR25 CR26 CR27 CR28	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010 EV10403560 DS17103010 DS17103010 DS17103010 DD15160330 DD15240330	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001μF ±10% Ceramic 0.01μF 35V Semicon 0.01μF Semicon 0.01μF Semicon 0.01μF Semicon 0.01μF Ceramic 15pF ±5% Ceramic 24pF ±5% Ceramic 0.01μF Ceramic
CR17 CR18 CR19 CR20 CR21 CR22 CR23 CR24 CR25 CR26 CR27 CR28	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	CT10600030 DD10050300 DK16102300 DK16102300 DS17103010 EV10403560 DS17103010 DS17103010 DS17103010 DD15160330 DD15240330	Trimming 6pF Ceramic 5pF ±0.25pF Ceramic 0.001μF ±10% Ceramic 0.01μF Elect 0.1μF 35V Semicon 0.01μF Semicon 0.01μF Semicon 0.01μF Ceramic 15pF ±5% Ceramic 24pF ±5%
	PP01 RP01 RP01 RP01 RP01 RP02 SM02 SM01 SM02 PP01 RP03 QP01 QP02 SP01 PR01 C001 C002 C003 C004 C005 C006 C007 C008 C009 CR04 CR11 CR12 CR13 CR14 CR15	DESIG. N JM01 1 JM02 1 JM03 1 JM04 1 JM05 1 SM01 1 SM02 1 PP01 1 RP01 1 RP01 1 RP02 1 RP02 1 RP03 7 RP01 1 C01 1 C002 1 SP01 1 PR01 1 C004 1 C005 1 C006 1 C007 1 C008 1 C009 1 CR04 1 CR09 1 CR04 1 CR09 1 CR09 1 CR10 1 CR11 1 CR12 1 CR13 1 CR14 1 CR15 1 CR16 1	JM01

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	REF. DESIG.	אדם	PART NO.		ESCRIPTION	
	DESIG.	N				
	CR30	1	DK16122300	Ceramic	0.0012µF ±10%	
	CR31	1	DD10020300	Caramic	2pF ±0,25p	F
	CR32	1	DK18103310	Ceramic	0.01µF	
	CR33	1	DD15820330	Caramic	82pF ±5%	
	CR34	1	DD15201360	Ceramic	200pF ±5%	
	CR35	1	DD15360300	Ceramic	36pF ±5%	
	CR36	1	D\$17683010	Semicon	0.068µF ±20%	
	CR37	1	DF16223300	Film	0.022µF ±10%	
	CR38	1 1	EA33601630	Elect	33µF	16V
	CR39	1	DS176B3010	Semicon	0.068µF ±20%	
:	CR40	1	DS17683010	Semicon	0.068µF ±20%	
	CR41	;	D\$17683010	Semicon		
	CR42	Ιi	DS17683010	Semicon	•	
	CR43	Ιi	DD15331360	Ceramic	330pF ±5%	
	CR44	1	DF16103300	Film	0.01μF ±10%	
į	CR45	1	DK16221300	Ceramiç	220pF ±10%	
	CR46	1	DK16102300	Ceramic	0.001µF ±10%	
	CR47	1	DS17683010	Semicon	0.068µF ±20%	
	CR48	1	DS17683010	Semicon	0.068µF ±20%	
	CR49	1	DS17683010	Semicon	0.068µF ±20%	
		l .				
	CR50	1 1	DS17683010	Semicon	0.068μF ±20%	
	CR51	1 1	DS17473010	Semicon	0.047μF ±20%	
	CR52	1 1	DD15201360	Ceramic	200pF ±5%	
	CR53	1 1	DF16223300 DF16103300	Film	0.022μF ±10%	
	CR54 CR55	;	DF16223300	Film Film	0.01µF ±10% 0.022µF ±10%	
	CR56	;	EV10403560	Elect	0.022μF 110æ 0.1μF	35V
	CR57	l i	EA10601690	Elect	10μF	16V
	CR58	i	DF16472300	Film	0.0047µF ±10%	
	CR59	Ιì	DF16472300	Film	0.0047µF ±10%	
					,	
	CR61	1	DD12100040	Ceramic	10pF ±1pF	
	CR62	1	DF16103300	Film	0.01µF ±10%	
	CR63	1	DD15331010	Ceramic	330pF ±5%	
	CR64	1	DD15201010	Ceramic	200pF ±5%	
	CR65	1	DF16103300	Film	0.01µF ±10%	
	CR66	1	EA22601090	Elect	22μF	10V
	CR67	1 1	DF16223300	Film	0.022µF ±10%	
	CR68	li	DK16471300 EV33600660	Ceramic Elect	470µF ±10%	6.3V
	CR70 CR71	Ιi	EV47501060	Elect	33μF 4.7μF	10V
	CR72	;	DF16103300	Film	0.01μF ±10%	104
	CR73	i	DF16223300	Film	0.022µF ±10%	
	CR74	i	DF16102300	Film	0,001µF ±10%	
	CR75	i	DF16223300	Film	0.022µF ±10%	
	CR76	ן ו	DF16102300	Film	0.001µF ±10%	
	CR78	1	DF16223300	Film	0.022µF ±10%	
	CR80	1	DF16103300	Film	0.01μF ±10%	
	CR81	1	EA10601690	Elect	10µF	16V
	CR82	1	DD15101350	Ceramic	100pF ±5%	
	CR83	1 1	EA10601690	Elect	10µF	16V
	CR84 CR85	1 1	EA10601690 DF16103300	Elect Film	10μF 0.01μF ±10%	16V
	CR86	;	DK16102300	Ceramic	0.001µF ±10%	
1	CR87	i	EV33502560	Elect	3.3µF	
	CR88	i	EV15600660	Elect	15μF	6.3V
ì	CR89	1	EQ10601620	Elect	10µF	16V
	CR90	1	EE22701650	Elect	220µF	16V
	CR91	1	DS17104010	Semicon	0.1µF ±20%	
	CR92	1	EA22702590	Elect	220µ F	25V
	CR93	1	EA10701090	Elect	100µF	10V
	CR94	1	DF16563300	Film	0.056µF ±10%	
	CR95	1 1	EA10505090	Elect	1μF	50V
	CR96	1	EA33601690	Elect	33µF	16V
	CR99	1	DF16333300	Film	0.033µF ±10%	
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REF. DESIG.	QTY	PART NO.	DESCRIPTION
	-		PR01-RESISTORS (All Resistors are ±5% and ½W)
RQ02	1	GD05104140	100ΚΩ
RQ03	Ιi	GD05153140	15KΩ
RQ04	Ιi	GD05103140	10ΚΩ
RQ05	l i	GD05103140	100Ω
RQ06	1 1	GD05470140	47Ω
RQ07	∣ i	GD05102140	1ΚΩ
HO08	1	GD05821140	820Ω .
RR06	1	GD05223140	22ΚΩ
RR10	1	GD05104140	100ΚΩ
RR11	1	GD05104140	100ΚΩ
RR12	1	GD05683140	68KΩ
RR13	1 1	GD05123140	12KΩ
RR14	1	GD05101140	100Ω
-015	١.	2005101140	100Ω
RR15	1	GD05101140 RA02030060	20KΩ Trimming
RR16	1	GD05473140	1 20KΩ Transming
RR17	1 1	GD05562140	5.6ΚΩ
RR19	;	GD05473140	47ΚΩ
RR20	1	GD05562140	5.6ΚΩ
RR21	1 1	GD05362140	47Ω
RR22	l i	GD05101140	100Ω
BR23	i	GD05222140	2.2ΚΩ
AR24	i	GD05222140	2.2ΚΩ
	1		l . <u></u>
RR25	1 !	GD05123140	12KΩ
RR26	1	GD05472140	4.7ΚΩ
RR27	1 !	GD05102140	1ΚΩ 100Ω
RR28	1 1	GD05101140 GD05222140	2.2ΚΩ
RR30	1 1	GD05222140	15KΩ
RR31	;	GD05153140	15KΩ
RR33	;	GD05222140	2.2ΚΩ
RR34	l i	GD05153140	15ΚΩ
RR35	i	GD05102140	1ΚΩ
B836	1	GD05101140	100Ω
RR37	1 1	GD05101140	100Ω
FIR38	i	GD05101140	100Ω
RR39		GD05152140	1.5ΚΩ
FIR40		GD05152140	1.5ΚΩ
RR41	1	GD05101140	100Ω
RR42	1	GD05562140	5.6ΚΩ
RR43	I .	GD05222140	2.2ΚΩ
RR44 RR45		GD05101140 GD05152140	
		'	
RR46		GD05102140	
RR47		GD05102140 GD05103140	
RR48 RR49		GD05103140	1
RR50		GD05562140	
RR51		GD05333140	
RR52		GD05474140	■
RR53		GD05102140	
RR54		GD05121140	120Ω
RR55		GD05102140	1ΚΩ
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REF.	QTY	PART NO.	DES	CRIPTION
DESIG.	N	PARTIC:		
				ļ
RR56	1 1	GD05472140	4.7KΩ	
RR57	1	GD05472140	4.7ΚΩ	
RR60	1	GD05473140	47KΩ	
RR61	1	RA01010080	100Ω	Trimming
RR62	1	GD05222140	2.2KΩ	
RR63	1	GD05473140 GD05222140	47ΚΩ 2.2ΚΩ	
RR64 RR65	1 1	GD05222140 GD05472140	4.7KΩ	
RR66	Ιi	GD05333140	33KΩ	
RR67	l i	GD05153140	15KΩ	
	ļ			
RR68	1	GD05101140	100Ω	T-:
RR70	!	RA04720090 GD05393140	4.7KΩ 39KΩ	Trimming
RR71 RR72	1 1	GD05393140	10KΩ	
RR73	l i	GD05104140	100ΚΩ	
RR74	l i	GD05151140	150Ω	
RR75	l i	GD05102140	1ΚΩ	
RR76	1	GD05333140	33KΩ	
RR77	1	GD05562140	5.6K Ω	Į.
RR78	1	GD05102140	1.2KΩ	
Boss	1	GD05221140	220Ω	
RR80 RR81	li	GD05682140	6.8KΩ	
RR82	Ìi	GD05562140	5.6KΩ	
RR83	Ιi	G005152140	1.5KΩ	
RR84	1	GD05103140	10KΩ	
RR98	1	GD05103140	10KΩ	
RR99	1	RA01040260	100KΩ	Trimming
			BBA1.SEMIC	CONDUCTORS
0.001	۱,	HF40048100	F.E.T.	3SK48
0002	Ιi	HD50001060	Diode	15V77
0003	1 1	HD50001060	Diode	15V77
	-	ļ		
QR01	1	HF900041A0	F.E.T.	3N201 (B)
QR02	1 1	HD20011050	Diode	1\$1555
QR03	!	HD10001050	Diode F.E.T.	1N60 3N201(B)
QR04 QR05	1 1	HF900041A0 HT304601B0	Transistor	2SC460(B)
QR06	;	HT304601B0	Transistor	2SC460(B)
QR07	1	HT304601B0	Transistor	2SC460(B)
QR08	1	HD10001050	Diode	1N60
QR09	1	HC10023060	IC	μPC577H
QR10	1	HC10023060	IC	μPC577H
	1 .	UD+00010E0	Diode	1N60
QR11 QR12	1 1	HD10001050	Diode	1N60
QR13	i	HT309451Q0	Transistor	2SC945(Q)
QR14	Ιi	HT309451Q0	Transistor	2SC945(Q)
QR15	1	HT309451Q0	Transistor	2SC945(Q)
QR16	1	HT30945100	Transistor	2SC945(Q)
QR17		HD10001050	Diode	1N60
QR18		HD10001050	Diode	1N60 2SC945(B)
QR19 QR20		HC10031010	Transistor IC	25C945(B) HA1366W
QH20	'	AC10031010	ا ا	(IAI300II
QR21	1	HD20011050	Diode	181555
QR22		HC10037050	IC	TA7063P
QR23	1	HD10001050	Diode	1N60
QR24		HD10001050	Diode	1N60
QR25		HV00002060	Varistor	VD1212
QR26		HD10001050	Diode	1N60 1S1555
QR30 QR31		HD20011050 HF200191B0	Diode F.E.T.	2SK19TM(GR)
		HP20019180	Diode	1S1555
QR32 AR33		HT107331R0	Transistor	2SA733(R)
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REF.	QTY	DARTEG	DECAMATION
DESIG.	N	PART NO.	DESCRIPTION
			- '''
			PR01-MISCELLANEOUS
FR01	5	XU410700M5	Crystal Filter, 10.7MHz
FR02	1	FF11070050	Ceramic Filter, SFE10,7MA
FR03 FR04]	FG455304F0 FG455304F0	Ceramic Filter, CFU455F Ceramic Filter, CFU455F
FR05	;	XU410700M5	Crystal Filter, 10.7MHz
JR01	1	YP06000890	Plug (3P) 3022-03A
JR02	1	YP06001470	Plug (5P) 3094-05A
JR03	1	YP06000880	Ptug Terminal
JR04 JR05	1 1	YT09010030 YT09010030	Terminal
JR06	i i	YT09010030	Terminal
JR07	1	YP06001150	Plug (8P) 3022-08A
JR08	1	YP06001480	Ptug (2P) 5045-02A
JR09 JR10	1 1	YP10002160 YJ10000520	Plug (2P) 5045-02A Jack (CTN-5)
JR11	l i	YP06000890	Plug (3P) 3022-03A
LQ01	i i	LA70280020	Ant Call DE Pro Ama
, LQ02	1	LA70190060	Ant. Coil, RF Pre-Amp.
LR01	1	LA70260010	Anti-con, in Amp.
LR02	1	LA70260020	Ant. Coil, Local
LR03 LR04	;	3648121020 3648121020	Link, Cavity Coil Link, Cavity Coil
LR05	1	3648121020	Link, Cavity Coil
LR06	1	L170038090	I.F.T. Coil, IF
LR07	1	L110010450	I,F,T, Coil
LR08	1	LI10010460	I.F.T. Coil
LR09	1	LC13940010	Choke Cojl, 390µH
LR10	ì	LC13940010	Choke Coil, 390µH
LR11	1	LC13940010	Choke Coil, 390µH
LR12	1	LC11040010	Choke Coil, 100µH
LR13 LR14	1 1	L170038090 L170030390	I.F.T. Coil, IF I.F.T. Coil, IF
LR15	l i	LC13940010	1.6.1. Coll, 15 Choke Coil, 390µH
LR16	i	LC11050040	Choke Coil, 1mH
XR01	1	XZ41024505	Crystal 10,245MHz
PS01	1	YF47240090	PS01-POWER SUPPLY CIRCUIT BOARD P.W. Board, Power Supply
			PS01-CAPACITORS
CS01 CS02	1 1	DK18103310 EA22601690	Ceramic 0,01µF +100% —0 Elect 22uF 16V
CS02	1	DK18103310	Elect 22µF 16V Ceramic 0.01µF +100% —0
CS04	i	DK18103310	Ceramic 0.01µF +100% —0
DCA.	,	C 105001010	PS01-RESISTORS
RS01 RS02	1 1	GJ05201010 GD05561140	200Ω ±5% 1W 560Ω ±5% ¼W
R\$03	1	GJ05561010	560Ω ±5% 1W
			PS01-SEMICONDUCTORS
QS01 QS02	1 1	HT313681B0	Transistor 2SC1368(B)
QS03	;	HD30017090 HD20001210	Zener BZ090 Diode 1S2473
Q\$04	i	HT313681B0	Transistor 2SC1368(B)
QS05	1	HD20001210	Diode 1S2473
QS06	1	HT70011100	Transistor JSP6009
Q\$07	1	HD20011050	Diode 1\$1555
QS08 QS10	1 1	HD20011050 HD20001210	Diode 1S1555 Diode 1S2473
4310	'		5154E 132973

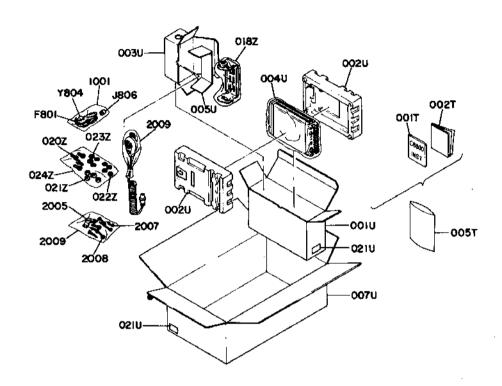
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REF. DESIG.	N	PART NO.	DESCRIPTION
DEGIG.	N		·
			PR01-PLUGS
JS01	1	YP06002110	Plug (20P)
JS02	1	YP06000880	Plug (6 P)
			PT01-TX YOUNGER
	!		CIRCUIT BOARD
PT01	1	YF47230120	P.W. Board, TX Younger
	Ì		_
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070	١.	DK40102240	PT01-CAPACITORS
CT01 CT02	1 1	DK18103310 DD15680330	Ceramic 0.01µF ±100% =0 Ceramic 68pF ±5%
CT03	;	DD15200330	Ceramic 20pF ±5%
CT04	li	DD10015300	Ceramic 1.5pF ±0.25pF
CT05	1	DD15200330	Ceramic 20pF ±5%
CT06	1	DD15510330	Ceramic 51pF ±5%
CT07	1	DK18103310	Ceramic 0.01µF +100% —0
CT08	1 1	DK18103310	Ceramic 0.01µF +100% -0
CT09 CT10	1	OK18103310 CT11050010	Ceramic 0.01µF +100%0 Trimming 12pF
0110	'	0111030010	Trinding 12p
CT11	1	DD10020300	Ceramic 2pF ±0.25pF
CT12	i	DK18103310	Ceramic 0.01µF +100% -0
CT13	1	DK18103310	Ceramic 0.01µF +100% -0
CT14	1	DK18103310	Ceramic 0.01µF +100%0
CT15	1 1	CT11050010	Trimming 12pF
CT16 CT17	1 1	DD10020300 DK18103310	Ceramic 2pF ±0.25pF Ceramic 0.01μF +100% —0
CT18	;	CT11050010	Trimming 12pF
CT19	l i	DD10050300	Ceramic 5pF ±0.25pF
CT21	1	DD15820300	Ceramic 82pF ±5%
CT22	1 1	DD15200300	Ceramic 20pF ±5%
CT23 CT24	1 1	DK18103310 EV47502560	Ceramic 0.01μF +100%0 Elect 4.7μF 25V
CT25	i	DK18103310	Ceramic 0.01µF +100% -0
CT26	ì	CT11050010	Trimming 12pF
CT27	1	DD11100300	Ceramic 10pF ±0.5pF
CT28	1	DD15360300	Ceramic 36pF ±5%
CT30	1 1	EA10601690	Elect 10µF 16V
CT31	'	DD11100300	Ceramic 10pF ±0.5pF
			PT01-RESISTORS
			(All Resistors are ±5% and ¼W)
RT01	1	GD05562140	5.6KΩ
RT02	1 1	GD05102140	1ΚΩ
RT03	1 1	GD05680140	6BΩ
RT04 RT05	1 1	GD05101140 GD05472140	100Ω 4,7KΩ
RT06	;	GD05472140 GD05561140	560Ω
RT07	;	GD05100140	10Ω
RT08	i	GD05680140	68Ω
RT09	1	GD05121140	120Ω
RT10	1	GD05100140	10Ω
RT11	!	GD05220140	2211
RT14	1	GD05561140	560Ω
		i	PT01-SEMICONDUCTORS
QT01	1	HT32347100	Transistor 2SC2347
QT02	t	HT32347100	Transistor 2SC2347
QT03	1	HT30994100	Transistor 2SC994
QT04	1	HT321180A0	Transistor 2SC2118
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REF.	αту	B4 B5 444	
DESIG.	N	PART NÓ.	DESCRIPTION
İ			PT01-MISCELLANEOUS
JT01	1	YP06001200	Plug (5P)
JT02	1	YP06000890	Plug (3P)
LT01	1	LW10188010	Doublar Coil, RF
LT02	l i	LW10188010	Doublar Coil, RF
LT03	1	LC16000010	Choke Coil (ST)
LT04	1	LC16000010	Choke Coil (5T)
LT05	1	LC16000010	Choke Coil (5T)
LT06 LT07	1	LC16000010 LC17000010	Choke Coil (5T) Choke Coil (4T)
LT08	i	LC16000010	Choke Coil (5T)
LT09	1	LC16000010	Choke Coil (5T)
LT10	1	LC16000010	Chake Cail (5T)
			PZ01-BACK-UP CIRCUIT BOARD
PZ01	1	YF47230040	P.W. Board, Back-up
			PZ01-CAPACITOR
CZ01	1	EA10601690	Elect 10µF 16V
RZ01	1	GD05392140	PZ01-RESISTORS (All Resistors are ±5% and ¼W) 3.9ΚΩ
RZ02	1	GD05562140	5.6KΩ
RZ03	1 1	GD05272140	2.7ΚΩ
RZ04 RZ05		GD05823140 GD05823140	82KΩ 82KΩ
RZ06	;	GD05823140	1ΚΩ
	· ·		
	١.		PZ01-SEMICONDUCTORS
0Z01 0Z02	1	HT107861R0 HT320211R2	Transistor 2SA786(R) Transistor 2SC2021LN
0202	l i	HT106731B0	Transistor 2SA673(B)
QZ04	i	HD30033090	Zener WZ052
	١.		
AZ01	1	ZK47230010	Unit, K DC-DC Converter P100-CTN-5 CIRCUIT BOARD
P001	1	YD37790020	P.W. Board, CTN-5
'**	`		
C101	1	EV47501660	CAPACITORS Elect 4.7µF, 16V
C102	Ι'n	EV33601060	Elect 33µF, 10V
C103	i	DF17333010	Film 0.033µF ±20%
C104	1	DF66101010	Film 100pF ±10%
C105	1	DF64272010	Film 2700pF ±2%
C106 C107		DF64272010 DF65432010	Film 2700pF ±2% Film 4300pF ±5%
C108	i	DF65242010	Film 2400pF ±5%
C109	1	EM10402510	Elect 0.1µF, 25V 25V
C110	1	EW10601010	Elect 10µF, 10V 10V
C111 C113	† 1	DD15500010 DK16471010	Ceramic 50pF ±5% Ceramic 470pF ±10%
"113	Ι'	5K104/1010	Octavine 410hL 11070
			RESISTORS
R101	1	RC10471140	470Ω ±10%, ¼W
R102 R103	1 1	GD05682140 GD05103140	6,8KΩ ±5%, ¼W 10KΩ ±5%, ¼W
R105	Ι¦	GD05103140	10KΩ ±5%, ½W
R106	1	GD05183140	18KΩ ±5%, ¼W
R107	1 1	GD05223140	22KΩ ±5%, ¼W
R108 R109	1 1	RA01040110 GD05103140	100KΩ Trimming 10KΩ ±5%, ¼W
R110	Ιi	GD05103140	10KΩ ±5%, 24V
R111	l i	GD05272140	2.7KΩ ±5%, ¼W
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REF.	QTY	PART NO.	DESC	RIPTION	
DESIG.	N		200		
R112	1	GD05104140	100KΩ	±5%,	12W
R113	1 1	GD05472140	4.7KΩ	±5%.	WW.
R114	i 1	GD05682180	6.8KΩ	±5%.	1/8W
R115	1 1	GD05473140	47ΚΩ	±5%.	14W
R116	1 1	GD05392180	3.9KΩ	±5%.	1/8W
R117	lil	GD05182180	1.8KΩ	±5%,	1/8W
R118	li	RA01030232			1/6VV
			10KΩ	Trimming	
R119	1	GD05473140	47KΩ	±5%,	¼W
R120	1 1	RA01040110	100ΚΩ	Trimming	
R121	1	GD05272180	2.7ΚΩ	±5%,	1/BW
R122	1	GD05121180	1 20 Ω	±5%,	1/8W
			,		
			MISCELLANE	OUS	
D101	1	HD20011050	Diode,	181555	
J101	1	YP10001060	Plug		
Q101	i	HT308281B0	Transistor,	2SC828(C)	
Q102	i i	HT308281B0	Transistor,		
Q102	1	1		2SC828(C)	
		HT308281B0	Transistor,	2SC828(C)	
Q104	1 1	HT308281B0	Transistor,	2SC828(C)	
Q105	1	HT308281B0	Transistor,	2SC828(C)	
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WW02	!	YB01000102	Connective Co		
WW03	1	YB01000680	Connective Co	rd	
WW04	1	YB01000420	Connective Co	rd	
WW05	1	YB01000430	Connective Co	rd	
WW06	1 1	YB01000440	Connective Co	rd	
WW07	l i	YB01000152	Connective Co		
	Ι'				
WW09	1 1	YB01000460	Connective Co	rd	
WW10	Ιi	YB01000470	Connective Co		
*****	Ι'	1 0010004/0	Gunnective CO	• • •	
1411414-	١.	1/201000155			
WW11	1 1	YB01000480	Connective Co		
WW12		YB01000490	Connective Co		
WW13	1	YB01000500	Connective Co		
WW14		YB01000510	Connective Co		
WW15	1	YB01000230	Connective Co	rd	
WW17	1	Y B00050040	Connective Co	rd	
WW18	1	YB01000590	Connective Co	rd	
	1	1			
WW20	1	YB01000270	Connective Co	rd	
		1			
144474	Ι'	, 50 1000560	Connective Co	•••	
	┸	1			
WW17	1 1 1 1 1	Y B00050040	Connective Co	rd rd rd rd rd rd	

(W01-99)	Assembly and Wiring
(T01-99)	Adjustment
(X01-00)	Correction

10.6 PACKAGING



ı		CT Y	PART NO.	DESCRIPTION	
	DESIG.	N	1 431 110.		
	001T	1	4785851010	Instructions	
	002T	i	4785856010	Circuit Diagram	
				_	
	***	_	0040005040		
	005T	1	9013025010	Polyethy Beg	
	001U	1	4723801050	Packing Case	
	002U	2	4723809010	Cushion	
	003U	1	4723801020	Packing Case	
	004U	1	9013340010	Polyethy Bag	
	005U	1	4723803010	Partitioner	
	007U	1/5	4723805040	Master Carton	
	021U	3	9526019010	Serial No. Card	
	018Z	1	9011340010	Polyethy Beg	
	020Z	4	5203052089	H. Head Boit, P. H5 x 20	
	021Z	4	53110503B9	Hexagon Nut	
	022Z	4	5404050280	Spring Washer	
	023Z	4	54020501B0	Flat Washer, P.	
	024Z	1	9011010010	Polyethy Bag	
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REF. DESIG.	CTT N	PART NO.	DESCRIPTION	
1001 2005 2007 2008 2009 F801 Y804 J806	1 1 4 4 2 1 1 1	9010818010 4723155010 51400312X0 51380330A0 9010608010 FS10600010 YC01500022 YP05000040	Polyethy Bag Hanger B.H. Tapped Screw B3 x 12 P.H. Tapped Screw P3 x 30 Polyethy Bag Fuse 6A A.C. Power Cord Plug, (9P)	

11. TECHNICAL SPECIFICATIONS

General
Transmission/reception frequency
band 144 MHz ~ 146 MHz
Type of emission
Microphone input impedance 600 ohms
Speaker impedance 8 ohms
Supply voltage 13.8 volts DC
Dimensions 168 mm (W) x 58 mm (H) x 240 mm (D)
Weight
Receiver section
Reception system Double superheterodyne
Intermediate frequencies 1st IF: 10.7 MHz
2nd 1F: 455 kHz
Sensitivity DX: -10 dB (20 dB QS)
-12 dB (12 dB SINAD)
NOR: 0 dB (20 dB QS)
-1 dB (12 dB SINAD)
LOC: +10 dB (20 dB QS)
+9 dB (12 dB SINAD)
Pass.bandwidth
Sensitivity Not less than 70 dB
Squelch sensitivity
AF output 2 watts (into 8 ohms at 10%
distortion)
AF load impedance 8 ohms
Non-signal current consumption 0.6 A
Transmitter section
Transmission power
Load impedance
Spurious ratio
Maximum frequency deviation 5 kHz Modulation Variable reactance modulation
AF response
Current consumption in transmission (Hi) 3.5 A
Current consumption in transmission fint 5.5 A
These specifications are a subject to change (in line with
future improvements) without notice.